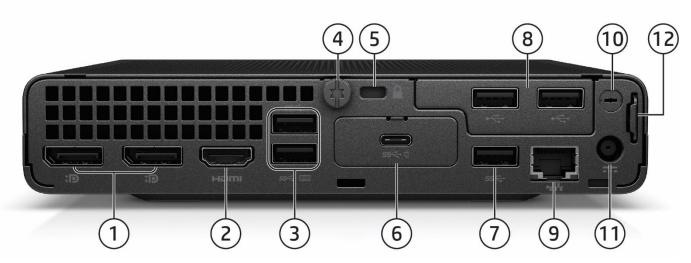
HP Elite Mini 800 G9 Desktop PC



- Type-C[®] SuperSpeed USB 20Gbps signaling rate port (charge support up to 5V/3A)
- 2. Type-A SuperSpeed USB 10Gbps signaling rate port
- 3. Type-A SuperSpeed USB 10Gbps signaling rate port (Charge support up to 5V/1.5A)
- 4. Combo Audio Jack with CTIA and OMTP headset support
- 5. Dual-state power button
- 6. Hard drive activity light



HP Elite Mini 800 G9 Desktop PC



- (2) Dual-Mode DisplayPort™ 1.4a (DP++) 1.
- 2. HDMI port 2.1
- 3. (2) Type-A SuperSpeed USB 10Gbps signaling rate port (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS)
- 4. Cover release thumbscrew
- 5. Standard cable lock slot (10 mm)
- 6. (1) Flex Port 1, choice of:
 - HDMI 2.1
- Fiber NIC 1Gbps1
- VGA
- Serial²
- DisplayPort™ 1.4a with HBR3
- Type-C™ SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode and 100W Power Intake
- Intel® I225-LM 2.5 Gigabit Network Connection LOM (non-vPro)
- Dual Type A SuperSpeed USB 5Gbps signaling rate port

- Type-A SuperSpeed USB 10Gbps signaling rate port
- (1) Flex Port 23, choice of:
 - NVIDIA GeForce 3050 Ti discrete GPU
 - Dual Type-A Hi-Speed USB 480Mbps signaling rate port
 - Serial
 - · Second external antenna
- RJ45 network connector 9.
- 10. External WLAN antenna opening³
- 11. Power connector
- Thunderbolt 3.0 with USB 4.0² 12. Retractable Padlock loop

Not Shown

Slots (1) Internal M.2 2230 connector for WLAN

(2) Internal M.2 SSD storage 2280 connector4

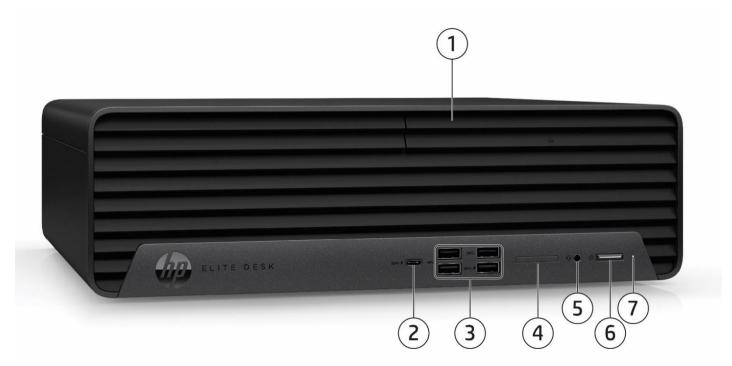
(1) 2.5- inch SATA drive Bay (not available on discrete graphics sku) Bays

Mounting Support for

> - VESA Sleeve Standalone - Ouick Release Bracket - B300/B500 Mounting bracket - Integrated Work Center Stand

- 1. Fiber NIC 1Gbps cards would not be available in some selected Europe countries and Korea. And Does not support PXE boot.
- 2. Sold separately or as an optional feature.
- 3. Must be configured at time of purchase.
- 4. When a 2nd M.2 SSD is installed after purchase in 65W CPU SKU configs, then After Market Option SATA Drive Bay Kit v2 (13L70AA) is needed.

HP Elite SFF 800 G9 Desktop PC

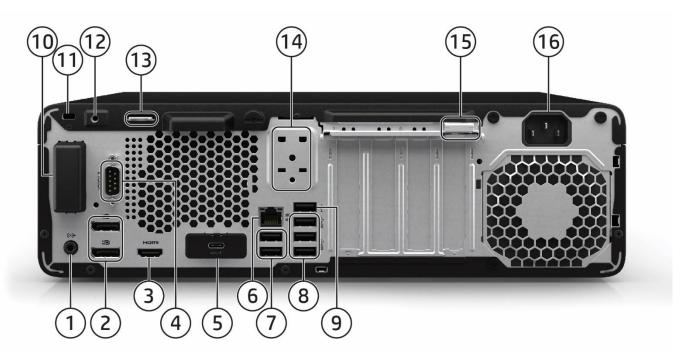


- 1. Slim optical drive (optional)
- 2. Type-C® SuperSpeed USB 20Gbps signaling rate port (charge support up to 5V/3A)
- 3. (4) Type A SuperSpeed USB 10Gbps signaling rate port (1 with charge support up to 5V/1.5A)
- 4. SD 4 Card Reader (optional)
- 5. Combo Audio Jack with CTIA and OMTP headset support
- 6. Dual-state power button
- 7. Hard drive activity light

Not Shown

- (1) PCI Express Gen4 x16 discrete graphics connectors
- (1) PCI Express x16 (wired as x4)
- (2) PCI Express x1
- (3) M.2 (1 as M.2 2230 socket for WLAN/BT and 2_as M.2 2280 socket for storage)

HP Elite SFF 800 G9 Desktop PC



- 1. Audio line-in/line-out connector
- (2) Dual-Mode DisplayPort™ 1.4a (DP++)
- HDMI port 1.4
- 4. Optional Serial port (shown here installed)
- 5. Optional port, choice of (shown here USB-C® installed):
 - DisplayPort™
 - HDMI 2.1
 - VGA
- Serial
- Dual Type-A SuperSpeed USB 5Gbps signaling rate port
- USB-C® SuperSpeed 10Gbps signaling rate port (Alt Mode DP 1.4 with 15W output)
- 6. RJ45 network connector
- (2) Type A Hi-Speed USB 480 Mbps signaling rate port with wake from S4/S5

- 8. (3) Type A SuperSpeed USB 5Gbps signaling rate port
- 9. (1) Type A Hi-Speed USB 480 Mbps signaling rate port
- 10. Internal WLAN antenna cover (optional, shown here not installed)
- 11. Standard cable lock slot
- 12. Business Lock (optional, shown here not installed)
- 13. Pad lock
- Intrusion sensor / hood lock (optional, shown here not installed)
- 15. Integrated keyboard/mouse wire hoop
- 16. Power cord connector

Not shown

Optional Ports

Thunderbolt[™] 3 port card¹

PS/2 & serial port card (connected to the mainboard via a flyer cable)¹

Parallel port1

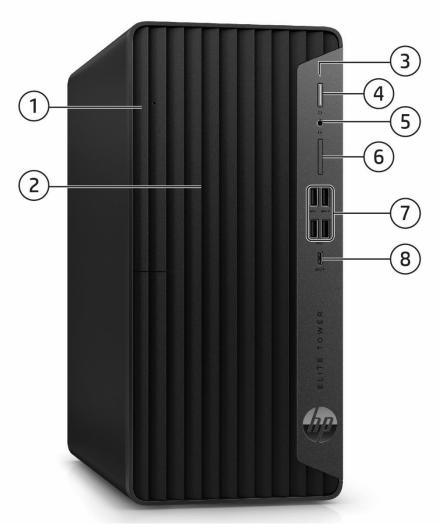
1. Each of the legacy port options would occupy one rear slot.

Bays

(2) 3.5" internal storage drive bay

(1) Slim optical drive bay (ODD or removable storage)

HP Elite Tower 800/880 G9 Desktop PC



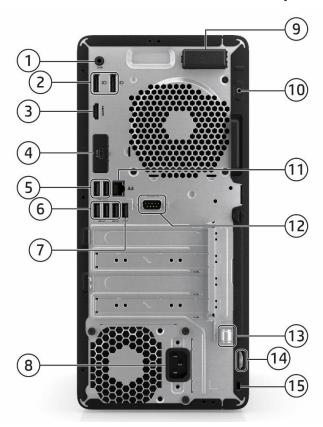
- 1. Slim optical drive bay (optional)
- 2. Slim optical bay for removable 2.5" HDD or M.2 SSD (optional)
- 3. Hard drive activity light
- 4. Dual-state power button
- 5. Combo Audio Jack with CTIA and OMTP headset support
- 6. SD card 4.0 reader (optional)
- 7. (4) Type-A SuperSpeed USB 10Gbps signaling rate port (1 with charge support up to 5V/1.5A)
- 8. Type-C[®] SuperSpeed USB 20Gbps signaling rate port (charge support up to 5V/3A)

Not Shown

Slots

- (1) PCI Express Gen4 x16 (wired as x4)
- (1) PCI Express Gen4 x16
- (2) PCI Express x1
- (3) M.2 (1 as M.2 2230 socket for WLAN/BT and 2 as M.2 2280 socket for storage)

HP Elite Tower Desk 800/880 G9 Desktop PC



- Audio line-in/line-out jack connector 1.
- 2. (2) Dual-Mode DisplayPort™ 1.4a (DP++)
- 3. HDMI port 1.4
- 4. Flex port, choice of (shown here HDMI installed):
 - DisplayPort™ 1.4
- Dual Type-A SuperSpeed USB
 - HDMI 2.1 VGA
- 5Gbps signaling rate port Serial
- USB-C® SuperSpeed USB 10Gbps signaling rate port (USB-C® option has alt mode DisplayPort™ 1.4 and 15W output)
- (2) Type A Hi-Speed USB 480 Mbps signaling rate port with 15. Standard cable lock slot wake from S4/S5

- 6. (3) Type A SuperSpeed USB 5Gbps signaling rate port
- 7. (1) Type A Hi-Speed USB 480 Mbps signaling rate port
- 8. Power cord connector
- 9. Internal WLAN antenna (optional, shown here installed)
- 10. Business Lock (optional, shown here not installed)
- 11. RJ-45 (network) jack
- 12. Serial port (optional, shown here installed)
- 13. Integrated keyboard/mouse wire hoop
- 14. Pad Lock

Not shown

Optional ports

Thunderbolt™ 3 card¹

PS/2 & serial port card (connected to mainboard via a flyer cable) 1

Parallel Port1

1. Each of the legacy options will occupy one rear slot.

Bays

- (2) 3.5" internal storage drive bay
- (2) Slim optical drive bay (optional, ODD and removable storage)



HP EliteOne 840 23.8 inch & 870 27 inch G9 All-in-One Desktop PC Touch/Non-Touch

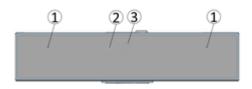


- 1. Camera (optional)
- 2. Speakers (optional)

3. Wireless Charger (in base) (optional)

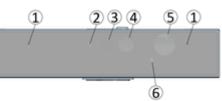
HP EliteOne 840 23.8 inch & 870 27 inch G9 All-in-One Desktop PC Touch/Non-Touch

5MP Webcam (optional)



Dual Microphones
 Webcam Light
 Webcam

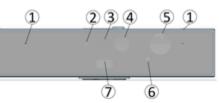
5MP Webcam +IR Sensor + CLS (optional)



Dual Microphones
 Webcam Light
 Webcam
 IR Sensor
 IR Light

6. CLS Sensor

16MP (4MP Binning) Swivel Webcam +IR Sensor + Time of Flight Sensor (TOF) (optional)



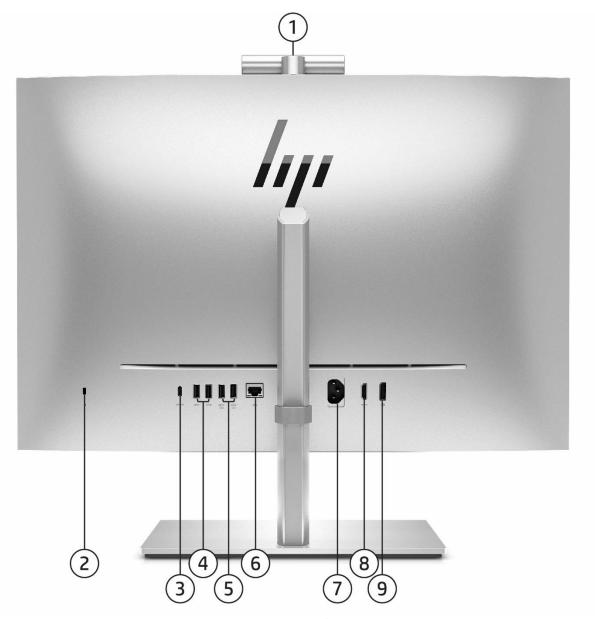
- 1. Dual Microphones
 - 2. Webcam Light
 - 3. Webcam
 - 4. IR Sensor
 - 5. IR Light
 - 6. CLS Sensor
 - 7. TOF Sensor

HP EliteOne 840 23.8 inch & 870 27 inch G9 All-in-One Desktop PC Touch/Non-Touch



- Type-A SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
- 2. Type-C® SuperSpeed USB 20Gbps signaling rate port (charge support up to (5V/3A)
- 3. Combo Audio Jack with CTIA and OMTP headset Support

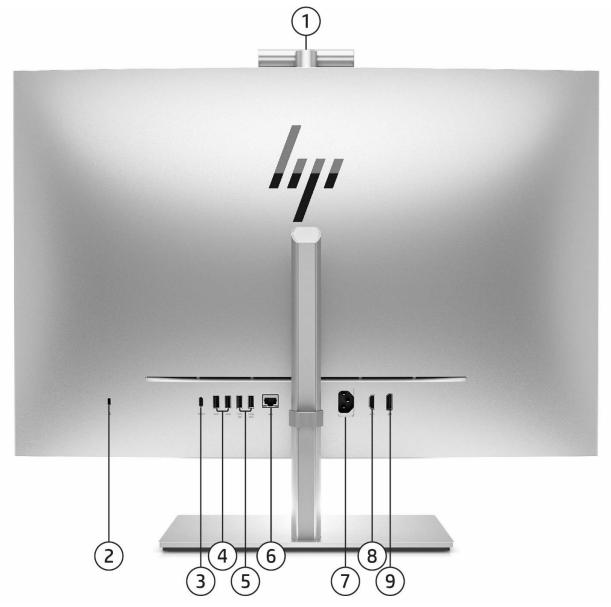
HP EliteOne 840 23.8 inch G9 All-in-One Desktop PC Touch/Non-Touch



Rear components and rear ports

- 1. Camera (optional)
- 2. Standard Cable Lock Slot
- Type-C[®] SuperSpeed USB 10Gbps signaling rate port (USB-C[®] option has alt mode DisplayPort[™] 1.4 and 15W output)
- 4. Type-A SuperSpeed USB 5Gbps signaling rate port (x2)
- 5. Type-A SuperSpeed USB 10Gbps signaling rate port (x2)
- RJ-45 network connector/jack
- 7. Power Connector
- 8. HDMI-in 1.4 connector
- 9. Dual-Mode DisplayPort™1.4 (DP++)

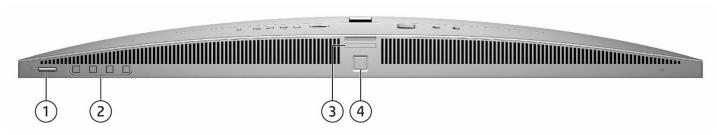
HP EliteOne 870 27 inch G9 All-in-One Desktop PC Touch/Non-Touch



Rear components and rear ports

- 1. Camera (optional)
- 2. Standard Cable Lock Slot
- 3. Type-C[®] SuperSpeed USB 10Gbps signaling rate port (USB-C[®] option has alt mode DisplayPort[™] 1.4 and 15W output)
- 4. Type-A SuperSpeed USB 5Gbps signaling rate port (x2)
- 5. Type-A SuperSpeed USB 10Gbps signaling rate port (x2)
- 6. RJ-45 network connector/jack
- 7. Power Connector
- 8. HDMI-in 1.4 connector
- 9. Dual-Mode DisplayPort™1.4 (DP++)

HP EliteOne 840 23.8 in & 870 27 in G9 All-in-One Desktop PC Touch/Non-Touch



Bottom

- 1. Dual-State Power button
- 2. OSD control buttons

- 3. SD card reader 4.0 (optional)
 - 4. Fingerprint Sensor (optional)

Not shown

Slots

- (1) internal M.2 PCIe x1 connector for optional wireless NIC
- (3) internal M.2 PCIe x4 connector for optional M.2 SSD storage

JFSΔ

Support for VESA 100 mounting system on back of PC chassis (mounting hardware sold separately)



Features

AT A GLANCE

- Choice of four form factors: Mini, Small Form Factor, Tower Desktop PC and All-In-One
- HP developed and engineered UEFI V2.7 BIOS supporting security, manageability, and software image stability
- Intel® Q670 chipset supporting Intel® 12th generation Core™ processors, featuring integrated Intel® UHD Graphics and Intel® vPro® Technology (available with Core i5- and above processors)
- Support for three (3) M.2 Storage slots (All-in-One)
- Intel® UHD graphics with optional NVIDIA discrete graphics (All-in-One, Mini)
- Intel® Ethernet Connection I219LM GbE LOM integrated network connection
- Intel® Wi-Fi 6E + BT5.2 (802.11AX 2x2) (All-in-One and Mini)⁵
- DDR5 Synchronous Dynamic Random Access Memory (SDRAM) (Transfer rates up to 4800 MT/s for Mini and AIO, up to 4400 MT/s for Tower and SFF)
- Support for up to 8 monitors via two standard DisplayPort™ 1.4 ports, one standard HDMI 2.1 (Mini) or HDMI 1.4
 (Tower/SFF), and a configurable Flex I/O port for video options and a discrete graphics card on Tower, SFF and Mini. All-in One supports up to two additional monitors via DisplayPort™, or Type-C® USB in alternate mode.
- Configurable FlexPort which provides the following choices: HDMI 2.1, Serial, VGA, DisplayPort™ 1.4, or USB Type-C® with DisplayPort™ 1.4 (USB Type-C® with DisplayPort™ 1.4 with Power Delivery [PD] on Mini), Thunderbolt 3 (PCIe card on TWR, SFF), Thunderbolt 3 with USB4.0 (port on Mini and will be ready in post launch), and Dual USB Type-A for (Tower, SFF and Mini). See Ports section for port availability by platform. FlexPort not supported on All-in-One.
- Power consumption of Desktop Mini PC varies per configuration, for the best user experience, please connect PC power cord while using USB-C® cable via Super Speed USB Type-C® port in the rear side of the platform.
- 2nd FlexPort available for configuration on the HP Elite Mini G9 Desktop PCs with the following ports: mini-DisplayPort™ ports and micro-HDMI (when configured with discrete graphic card), Serial, Dual USB Type-A, and 2nd external antenna.
- Configurable NVIDIA® GeForce® discrete graphics card with (3) mini-DisplayPort™ ports and (1) micro-HDMI video port for Mini to support up to (8) monitors with 4K resolution
- Configurable, NVIDIA® GeForce® VR ready and NVIDIA® Quadro® discrete graphics on Tower¹
- Models can be configured with multiple data drives in a RAID array and support RAID 1 configured from factory. Systems
 can be put into RAID1 and RAID0 configurations outside of the factory by adding the appropriate 2nd storage device. To
 enable RAID1 function, system should be configured with the same type and capacity storage device. SFF and TWR
 desktop PCs support a 3rd non-RAID drive when 2 drives are configured with RAID; the Mini desktop PC does not support a
 3rd non-RAID drive when 2 drives are configured with RAID.
- Audio by Bang & Olufsen (All-in-One)
- Integrated Low Blue Light Panels on All-in-One
- Enhanced Security with HP Security Suite (Refer to Security Section for details)
- ENERGY STAR® certified. EPEAT® registered where applicable. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.
- CCC. CECP and SEPA Certified (TWR/SFF/Mini Desktop/All-in-One)
- TCO Edge for All-in-One TCO (Tower/SFF/Mini Desktop)
- PC chassis and all internal components and modules are manufactured with low halogen content
- Dust filter available for the following platforms (Mini Desktop PC SFFs and Tower)
- Protected by HP Services, including limited warranties up to 1-1-1 (terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support
- Compliance with CE (Class B) / FCC (Class B) / UL (UL60950-1 /UL62368-1) / CSA (CSA C22.2 No.60950-1-07 / CSA C22.2 No.62368-1-14) / ICES-003 / CCC / VCCI (Class B) / KCC (Class B)

1. VR-ready as optional feature, specific configuration to support: 800 TWR: Nvidia GeForce 3070 LRH card

NOTE: See important legal disclosures for all listed specs in their respective feature sections



Features

PRODUCT NAME

HP Elite Mini 800 G9 Desktop PC HP Elite SFF 800 G9 Desktop PC HP Elite Tower 800/880 G9 Desktop PC HP EliteOne 840 23.8 inch G9 All-in-One Desktop PC HP EliteOne 870 27 inch G9 All-in-One Desktop PC

OPERATING SYSTEM

Preinstalled Windows 11 Pro¹

Windows 11 Pro Education¹

Windows 11 Home - HP recommends Windows 11 Pro for business¹

Windows 11 Home Single Language - HP recommends Windows 11 Pro for business¹ Windows 11 Pro (Windows 11 Enterprise available with a Volume Licensing Agreement)¹

Windows 10 Pro (available through downgrade rights from Windows 11 Pro)^{1,2}

FreeDOS

1. Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

2. This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

CHIPSET

	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Q670	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>



Features

PROCESSORS

Intel® 12 th Generation Core™ Processors	<u>Mini</u>	<u>SFF</u>	TWR	<u>AiO</u>
Intel® Core™ i9-12900 Processor with Intel® UHD Graphics 770 (2.4GHz, up to 5.1 GHz with Intel® Turbo Boost Max Technology¹, 30MB L3 cache, 16 cores) 65W ^{2.} Supports Intel® vPro® Technology³	х	x	х	х
Intel® Core™ i9-12900T Processor with Intel® UHD Graphics 770 (1.4GHz, up to 4.9GHz with Intel® Turbo Boost Technology¹, 30MB cache, 16 cores) 35W². Supports Intel® vPro® Technology³	Х			
Intel® Core™ i7-12700 processor with Intel® UHD Graphics 770 (2.1 GHz, up to 4.9 GHz with Intel® Turbo Boost Technology¹, 25 MB L3 cache, 12 cores) 65W² Supports Intel® vPro® Technology³	х	х	x	x
Intel® Core™ i7-12700T Processor with Intel® UHD Graphics 770 (1.4 GHz, up to 4.7 GHz with Intel® Turbo Boost Technology¹,25MB cache, 12 cores) 35W². Supports Intel® vPro® Technology³	х			
Intel® Core™ i5-12600 processor with Intel® UHD Graphics770 (3.3 GHz, up to 4.8 GHz with Intel Turbo Boost Technology¹, 18 MB cache, 6 cores) 65W²-Supports Intel® vPro® Technology³	х	x	х	x
Intel® Core™ i5-12600T processor with Intel® UHD Graphics 770 (2.1GHz, up to 4.6 GHz with Intel Turbo Boost Technology¹, 18 MB cache, 6 cores) 35W². Supports Intel® vPro® Technology³	х			
Intel® Core™ i5-12500 processor with Intel® UHD Graphics 770 (3.0GHz, up to 4.6 GHz with Intel Turbo Boost Technology¹, 18 MB cache, 6 cores) 65W². Supports Intel® vPro® Technology³	х	х	х	х
Intel® Core™ i5-12500T processor with Intel® UHD Graphics 770 (2.0GHz, up to 4.4 GHz with Intel Turbo Boost Technology¹, 18 MB cache, 6 cores) 35W². Supports Intel® vPro® Technology³	х			
			11	
Intel® Core™ i5-12400 processor with Intel® UHD Graphics 730 (2.5 GHz, up to 4.4 GHz with Intel Turbo Boost Technology¹, 18 MB cache, 6 cores) 65W².	X	х	x	x
Intel® Core™ i5-12400T processor with Intel® UHD Graphics 730 (1.8GHz, up to 4.2 GHz with Intel Turbo Boost Technology¹, 18 MB cache, 6 cores) 35W².	х			
Intel® Core™ i3-12300 processor with Intel® UHD Graphics 730 (3.5GHz, up to 4.4 GHz with Intel Turbo Boost Technology¹, 12 MB cache, 4 cores) 65W².	х	x	х	x
Intel® Core™ i3-12300T processor with Intel® UHD Graphics 730 (2.3GHz, up to 4.2 GHz with Intel Turbo Boost Technology¹, 12 MB cache, 4 cores) 35W²-	х			



Features

Intel® Core™ i3-12100 processor with Intel® UHD Graphics 730 (3.3GHz, up to 4.3 GHz with Intel Turbo Boost Technology¹, 12 MB cache, 4 cores) 65W².	х	Х	Х	Х
Intel® Core™ i3-12100T processor with Intel® UHD Graphics 730 (2.2GHz, up to 4.1 GHz with Intel Turbo Boost Technology¹, 12 MB cache, 4 cores) 35W².	х			

- 1. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system. See http://www.intel.com/technology/turboboost for more information.
- 2. Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a configuration measurement of higher performance.
- 3. For full Intel® vPro® functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or WLAN card and TPM 2.0 are required. See http://intel.com/vpro. Some functionality of vPro technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependent on 3rd party software providers. Compatibility of this generation of Intel vPro technology-based hardware with future "virtual appliances" is yet to be determined.

GRAPHICS

0p

Integrated Intel® Graphics	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	
Intel® UHD Graphics 770 (integrated in 12 th gen Corei5-12500T and above)	Х	X	Х	Х	
Intel® UHD Graphics 730 (integrated in 12 th gen Core i5-12400(T), and i3)	х	х	х	Х	

tional Discrete Graphics Solutions	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
NVIDIA® GeForce® RTX 3070 8GB LHR Graphics Card ¹			X	
NVIDIA® GeForce® RTX 3050Ti 4GB Graphics Card²	Х			Х
NVIDIA® GeForce® RTX 3060 12GB Graphics Card¹			X	
NVIDIA® T400 2GB 3 mDP Graphics Card		Х	X	
NVIDIA® T400 4GB Graphics Card		х	X	

- 1. Requires 400W or 500W chassis
- 2. Only available on the Desktop Mini with a 35W Processor and supports (3) Mini DP 1.4 Ports and (1) Micro —HDMI 2.0 port in order to drive up to 8 displays directly on the Desktop Mini.

lapters and Cables	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP DisplayPort™ Cable	Х	Х	X	Х
HP DisplayPort™ to DVI-D Adapter				Х
HP DisplayPort™ to HDMI True 4K Adapter	X	Х	X	Х
HP DisplayPort™ to VGA Adapter	X	Х	X	Х
HP USB to Serial Port Adapter	X	Х	X	Х
HP USB-C® to HDMI Adapter				Х
HP USB-C® to DisplayPort™ Adapter				Х
HP HDMI Standard Cable Kit (HDMI)		Х	X	Х
50cm USB-C Cable (100W power delivery)	X			



Features

STORAGE

3.5 inch SATA Hard Disk Drives (HDD)	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
500GB* 7200RPM 3.5in SATA HDD		Х	X	
1TB* 7200RPM 3.5in SATA HDD		Х	Х	
2TB* 7200RPM 3.5in SATA HDD		Х	Х	

2.5 inch SATA Hard Disk Drives (HDD)	<u>Mini</u>	<u>SFF**</u>	<u>TWR**</u>	<u>AiO</u>
500GB* 7200RPM 2.5in SATA HDD	х	X	X	
1TB* 7200RPM 2.5in SATA HDD	Х	X	X	
2TB* 5400RPM 2.5in SATA HDD	Х	X	X	
500GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD**	х	Х	Х	

^{*} Storage DriveLock does not work with Self Encrypting or Optane based storage.

^{** 2.5} inch SATA Hard Disk Drives are only available with the removable Hard Disk Drive carrier, and as the primary drive only.

PCIe NVMe Solid State Drives (SSD)	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
256GB* M.2 2280 PCIe NVMe SSD	X	Х	X	X
512GB* M.2 2280 PCIe NVMe SSD	X	Х	X	Х
1TB* M.2 2280 PCIe NVMe SSD	X	Х	X	
256GB* M.2 2280 PCIe NVMe Three Layer Cell SSD	X	Х	Х	Х
512GB* M.2 2280 PCIe NVMe Three Layer Cell SSD	X	Х	X	Х
1TB* M.2 2280 PCIe NVMe Three Layer Cell SSD	X	Х	X	Х
2TB* M.2 2280 PCIe NVMe Three Layer Cell SSD	X	Х	Х	Х
256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD**	X	Х	X	Х
512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD**	Х	Х	Х	Х

^{*} For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software

^{**}Storage DriveLock does not work with Self Encrypting or Optane based storage

Optical Disc Drives	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP 9.5mm Slim DVD-ROM Drive ¹		X	X	
HP 9.5mm Slim DVD Writer Drive ¹		X	Х	

^{1.} HD-DVD disks cannot be played on this drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

Medi	a Card Reader	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
	SD 4.0 with 5-in-1 Interface (Supports SD, SDXC, SDHC, UHS-I, UHS-II)		Х	Х	X

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows) of system disk is reserved for the system recovery software.



Features

MEMORY

Memory Type	<u>Mini</u>	SFF*	TWR*	<u>AiO</u>
DDR5-4800 (Transfer rates up to 4800 MT/s), Max 64 GB, 2 SO-DIMM	X			X
DDR5-4800 UDIMM module, Max 128 GB, 4 DIMM slots		Х	X	

^{*}NOTE: Memory modules support data transfer rates up to 4800 MT/s; system speed up to 4400 MT/s, following Intel's design guideline. Actual data rate is determined by the system configuration.

^{*}NOTE: All memory slots are customer accessible / upgradeable.

mory Configuration	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
8GB (1 x 8GB)	Х	Х	X	Х
16GB (2 x 8GB)	Х	Х	Х	Х
32GB (4 x 8GB)		Х	X	
16GB (1 x 16GB)	Х	Х	X	Х
32GB (2 x 16GB)	Х	Х	X	X
64GB (4 x 16GB)		Х	Х	
32GB (1 x 32GB)	Х	Х	X	X
64GB (2 x 32GB)	Х	Х	Х	Х
128GB (4 x 32GB)		Х	Х	



^{*}NOTE: System architecture design is 2 DIMMS per channel and the population starts from the furthest memory slot from the processor.

^{*}NOTE: Symmetric configurations are required for the 2 DIMMs within the same memory channel.

^{*}NOTE: To achieve optimal memory speed, HP strongly recommends to use identical memory modules (e.g., same capacity, same part number and from the same supplier) within the same memory channel

Features

NETWORKING/COMMUNICATIONS

Ethernet (RJ-45)		<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	
Intel® I219-L	M 1 Gigabit Network Connection LOM (vPro)	Х	Х	Х	Х	
Intel® Ethern	net Network Adapter I225-T1 (optional)	Х	Х	Х		

Wireless	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Intel® Wi-Fi 6E¹ AX211 + BT5.2 (802.11AX 2x2 vPro, supporting gigabit data rate²)	X	Х	Х	X
Intel® Wi-Fi 6E¹ AX211 + BT5.2 (802.11AX 2x2 non-vPro, supporting gigabit data rate²)	х	Х	X	
Realtek RTL8852BE 802.11ax ³ 2x2 Wi-Fi [®] 6 ² + BT5.2	Х	Х	Х	X

^{1.} Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

NOTE: Intel Wi-Fi 6E modules are available on Elite Tower and SFF G9, but the 6GHz band is not available.

NOTE: WiFi-6E might restrict by local regulation and the current eligible regions are: USA, South Korea, Costa Rica, El Salvador, Guatemala, Honduras, Peru and UAE. HP will enable countries in the future by upgrading BIOS in default.

KEYBOARDS AND POINTING DEVICES

Keyboards	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u> AiO</u>
HP Wired Desktop 320K Keyboard	X	X	X	X
HP USB Business Slim Wired SmartCard CCID Keyboard	X	Х	X	X
HP Business Slim PS/2 Wired Keyboard		Х	Х	
HP 125 Wired Keyboard	X	X	X	X
HP 125 AntiMicrobial Wired Keyboard (China Only)	X	Х	Х	X

Keyboard and Mouse Combo	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP 655 Wireless Keyboard and Mouse Combo	X	X	Х	Х

se	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
HP Wired 320M Mouse	Х	X	X	Х
HP PS/2 Mouse		X	X	
HP Wired 125 Mouse	Х	X	X	Х
HP Wired 128 Laser Mouse	Х	X	X	Х
HP Wired 125 Antimicrobial Mouse (China only)	Х	Х	Х	Х

^{2.} Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

^{3.} Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

Features

SECURITY

	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
TPM 2.0 endpoint security controller (Infineon SLB9672) shipped with Windows 10. Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified.	х	х	x	x
Solenoid Lock & Intrusion Sensor (optional)		X	X	
Intrusion Sensor for Mini/AiO (integrated in the PCA, can be enabled/disabled through BIOS)	Х			X
Support for chassis cable lock devices	X (10 mm barrel or smaller)	х	х	х
Support for chassis padlocks devices	X	X	X	
HP Fingerprint Sensor (optional)				X
SATA port disablement (via BIOS)	Х	X	X	
Serial, USB enable / disable (via BIOS)	X	X	X	X
Serial, parallel, USB enable / disable (via BIOS)	X	X	X	Х
Optional USB Port Disable at factory (user configurable via BIOS)	X	X	X	X
Removable media write/boot control	Х	X	X	Х
Power-on password (via BIOS)	Х	X	X	Х
Setup password (via BIOS)	Х	Х	Х	Х



Features

PORTS

I/O Ports – Internal Ports	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
PCI Express 4.0 x16		1	1	
PCI Express 3.0 x16 (wired as x4)		1	1	
PCI Express 3.0 x1		2	2	
SATA port		4	4	
Internal SATA storage connector	1			
M.2 PCIe	(1) M.2 PCIe3 x1 2230 (for WLAN) (1) M.2 PCIe4 x4 2280 (for storage) (1) M.2 PCIe4 x4 2280 (for storage)	(1) M.2 PCIe 3 x1 2230 (for WLAN) (2) M.2 PCIe 4 x4 2280 (for storage)	(1) M.2 PCle 3 x1 2230 (for WLAN) (2) M.2 PCle 4 x4 2280 (for storage)	(1) M.2 WLAN+BT Combo; (3) M.2 2280 for NVME SSD storage. One attached to CPU PCIe Gen 4.0, Two attached to PCH PCIe Gen 3.0

1. M.2 SSD attached to CPU is PCIe Gen 4, the other two M.2 are PCIe Gen 3 (AIO) **NOTE**: For Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after-market option).

andard User Accessible Ports	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Type-A Hi-Speed USB 480Mbps signaling rate port		3 (rear)	3(rear)	
Type-A SuperSpeed USB 5 Gbps signaling rate port		3 (rear)	3 (rear)	2 (rear)
Type-A SuperSpeed USB 10 Gbps signaling rate port	2(front) 3 (rear)	4 (front)	4 (front)	2 (rear) 1 (side)
Type-C [®] SuperSpeed USB 10Gbps signaling rate port (USB-C [®] option has alt mode DisplayPort™ 1.4 and 15W output)				1 (rear)
Type-C® SuperSpeed USB 20Gbps signaling rate port	1 (front)	1 (front)	1 (front)	1 (side)
Video	2 DisplayPort™ 1.4a 1 HDMI 2.1	2 DisplayPort™ 1.4a 1 HDMI 1.4	2 DisplayPort™ 1.4a 1 HDMI 1.4	1 DisplayPort™ 1.4 (rear) 1 USB Type-C® with alt mode display or 15W output) (rear) 1 HDMI-In (rear)
Audio	1 Combo Audio Jack with CTIA and OMTP headset support (front)	1 Universal Audio Jack with CTIA and OMPT headset support (front); 1 Audio-Line- in/Line out (rear)	1 Universal Audio Jack with CTIA and OMPT headset support (front); 1 Audio-Line- in/Line out (rear)	1 CTIA/OMTP UAJ (side)



Features

lexible Port 1, choice of <u>one</u> of the wing:	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Dual Type-A SuperSpeed USB 5 Gbps signaling rate port	1	1	1	
Type-C [®] SuperSpeed USB 10Gbps signaling rate port	1 SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode and power intake via USB Type-C® Power Delivery up to 100W	1	1	
Thunderbolt™ 3.0 with USB 4.0 ²	1 ³	1	1	
Video	1 DisplayPort™ 1.4a <u>or</u> HDMI 2.1 <u>or</u> VGA	1 DisplayPort™ 1.4a <u>or</u> HDMI 2.1 <u>or</u> VGA	1 DisplayPort™ 1.4a <u>or</u> HDMI 2.1 <u>or</u> VGA	
Serial	1 ³	1	1	
Fiber NIC Adapter	(1) 1 Gbps NIC	_		
RJ-45 Ethernet NIC	(1) 2.5GbE	-		

- 2. Occupies a PCIe slot on TWR/SFF. Available in Q3, 2021.
- 3. Sold separately or as an optional feature.

1) Flexible Port 2, choice of <u>one</u> of the ollowing:	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Type-A USB	2 Type-A Hi-Speed USB 480Mbps signaling rate port			
Serial	1			
Discrete Graphics	1			
2 nd External antenna	1			

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

Bays	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>
Slim Optical Disc Drive (ODD or removable storage)		1	2	
SD Card Reader		1	1	1
2.5" Internal Storage Drive	14			
3.5" Internal Storage Drive		2	2	

4. SATA 2.5" internal storage drive cannot be selected if discrete graphic card is selected.



Features

USB SPECIFICATION AND MARKETING NAME MAPPING TABLE

Marketing Name	Technical Terminology
Hi-Speed USB 480Mbps signaling rate	USB 2.0
SuperSpeed USB 5Gbps signaling rate	USB 3.2 Gen 1
SuperSpeed USB 10Gbps signaling rate	USB 3.2 Gen 2
SuperSpeed USB 20Gbps signaling rate	USB 3.2 Gen 2x2



Features

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Software

HP Easy Clean¹

HP OuickDrop²

HP PC Hardware Diagnostics UEFI

HP Desktop Support Utilities

HP Privacy Settings

HP Setup Integrated 00BE

HP Support Assistant³

HP Touchpoint Customizer for Commercial

myHP

HP Notifications

HP Connection Optimizer

HP Smart Support⁴

Buy Microsoft Office (sold separately)

Manageability Features

HP Connect for Microsoft Endpoint Manager⁵

HP Image Assistant Gen5 (download)

HP Manageability Integration Kit (download)6

HP Client Management Script Library (download)

HP Patch Assistant (download)⁷

HP Driver Packs (download)

HP Cloud Recovery⁸

HP Client Catalog (download)

Security Management

HP Wolf Security for Business9:

HP Sure Click¹⁰

HP Sure Sense 211

HP Sure Run Gen5¹²

HP Sure Recover Gen513

HP Sure Start Gen714

HP Tamper Lock

HP Sure Admin¹⁵

HP Client Security Manager Gen7¹⁶

BIOS

HP BIOSphere Gen6¹⁷

HP Secure Erase¹⁸

HP DriveLock & Automatic DriveLock

BIOS Update via Network

Absolute Persistence Module¹⁹

TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)

- 1. HP Easy Clean requires Windows 10 RS3 and will disable the keyboard, touchscreen, and clickpad only. Ports are not disabled. See user guide for cleaning instructions.
- 2. HP Quick Drop requires Internet access and Windows 10 or higher PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.
- 3. HP Support Assistant requires Windows and Internet Access
- 4. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, or it can be downloaded. For more information about how to enable HP Smart Support or to download, please visit http://www.hp.com/smart-support.
- 5. HP Connect for Microsoft Endpoint Manager is available from the Azure Market Place for HP Pro, Elite, Z and Point-of-Sale PCs managed with Microsoft Endpoint Manager. Subscription to Microsoft Endpoint Manager required and sold separately. Network connection required.



Features

- 6. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- 7. HP Patch Assistant available on select HP PCs with the HP Manageability Kit that are managed through Microsoft System Center Configuration Manager. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html.

 8. HP Cloud Recovery is available for Z by HP, HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail, please refer to: https://support.hp.com/us-en/document/c05115630.
- 9. HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features and OS requirement.
- 10. HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.
- 11. HP Sure Sense is available on select HP PCs with Windows 10 Pro, Windows 10 Enterprise, Windows 11 Pro, or Windows 11 Enterprise OS.
- 12. HP Sure Run Gen5 is available on select HP PCs and requires Windows 10 and higher.
- 13. HP Sure Recover Gen5 with Embedded Reimaging is an optional feature which requires Windows 10 and higher must be configured at purchase. You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module
- 14. HP Sure Start Gen7 is available on select HP PCs and requires Windows 10 and higher
- 15. HP Sure Admin requires Windows 10 or higher, HP BIOS, HP Manageability Integration Kit from http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store
- 16. HP Client Security Manager Gen7 requires Windows and is available on the select HP Elite and Pro PCs.
- 17. HP BIOSphere Gen6 features may vary depending on the platform and configuration.
- 18. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- 19. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: https://www.absolute.com/about/legal/agreements/absolute/.



Features

UNIT ENVIRONMENT AND OPERATING CONDITIONS

ENERGY STAR® certified models available

ENERGY STAR® certified. EPEAT® registered where applicable. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.

Low halogen (chassis, all internal components and modules)1

TAA compliant models available

1. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit
 is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign
 matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 50° to 95° F (10° to 35° C)²

Non-operating: -22° to 149° F (-30° to 65° C)

Relative Humidity Operating: 10% to 90% (non-condensing at ambient)

Non-operating: 5% to 95% (non-condensing at ambient)

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50000ft (15240 m)

2. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.



Features

ENVIRONMENTAL & INDUSTRY

HP Elite Mini 800 G9 Desktop PC

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR® US Federal Energy Management Program (FEMP) EPEAT® Gold registered in the United States. See http://www.epeat.net for registrati status in your country. TCO Certified China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label Commission Regulation (EC) No 617/2013 (ErP Lot 3)			
Sustainable Impact Specifications	 Ocean-bound plastic in Frame, Panel and Speaker 40% post-consumer recycled plastic Low halogen Outside Box and corrugated cushions are 100% sustainably sourced and recyclable Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable Bulk packaging available 			
System Configuration	The configuration used for the End Desktop model is based on a "Typ		oise Emissions data for the	
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal (Short idle)	7.38 W	7.49 W	7.18 W	
Normal Operation (Long idle)	2.34 W	2.42 W	2.18 W	
Sleep	2.26 W	2.34 W	2.1 W	
Off	0.63 W	0.71 W	0.47 W	
Heat Dissipation*	NOTE: Energy efficiency data listed is family. HP computers marked with the Environmental Protection Agency (EP not offer ENERGY STAR® certified cont PC featuring a hard disk drive, a high e	e ENERGY STAR® Logo are compliant v A) ENERGY STAR® specifications for co figurations, then energy efficiency da	with the applicable U.S. Omputers. If a model family does ta listed is for a typically configured	
Normal Operation	25.2 BTU/hr	25.6 BTU/hr	24.6 BTU/hr	
(Short idle)	25.2 810/11	25.0 810/11	24.0 810/11	
Normal Operation (Long idle)	8 BTU/hr	8.3 BTU/hr	7.5 BTU/hr	
Sleep	7.7 BTU/hr	8 BTU/hr	7.2 BTU/hr	
Off	2.2 BTU/hr 2.4 BTU/hr 1.6 BTU/hr			
	NOTE: Heat dissipation is calculated b one hour.	ased on the measured watts, assumin	ng the service level is attained for	
Declared Noise Emissions (in accordance with	Sound Power		Sound Pressure (L _{pAm} , decibels)	
ISO 7779 and ISO 9296)	(L _{WAd} , bels)		(L _{pAm} , decibels)	



Features

Fixed Disk – Random writes		2.7		17
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:			ral years. Upgradeable
	production.	are available throughout the warranty period a		
Additional Information	dire • This	product is in compliance with the Restrictions ctive - 2011/65/EC. HP product is designed to comply with the Wa		
	• This	EE) Directive – 2002/96/EC. product is in compliance with California Propo king Water and Toxic Enforcement Act of 1980		ate of California; Safe
	• This	product is in compliance with the IEEE 1680 (I://www.epeat.net	EPEAT) stand	
	ISO ²	itics parts weighing over 25 grams used in the 1043. I product is 92.7% recycle-able when properly		
	• IIIIs	product is 32.7 % recycle-able when property	uisposeu oi a	at end of the.
Packaging Materials	External:	PAPER/Corrugated		405 g
		PAPER/Molded pulp		74 g
	Internal:	PLASTIC/Polyethylene low density - LDPE backaging material contains at least 80.0% re	cyclod contor	<u>5 g</u>
		ted paper packaging materials contains at lea		
	products wo legislation in We believe the elimination of including PV and electron	In the European Union (EU) Restriction of Hazardwide through the HP GSE. HP has contribute Europe, as well as China, India, and Vietnam. The RoHS directive and similar laws play an impost substances of concern. We have supported to BFRs, and certain phthalates—in future Rofics products.	ed to the deve ortant role in the inclusion IS legislation	elopment of related n promoting industry-wide of additional substances— that pertains to electrical
	requirements for virtually all relevant products by July 2013, and we will continue to exter scope of the commitment to include further restricted substances as regulations continue evolve.			gulations continue to
	To obtain a c	opy of the HP RoHS Compliance Statement, se	e: HP RoHS p	osition statement.
Material Usage	This product does not contain any of the following substances in excess of regulatory to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plast • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde		f):	
	 Lead carbo Lead and Lo Mercuric Ox 	ed Diphenyl Methanes nates and sulfates ead compounds kide Batteries ishes must not be used on the external surface e user.	e designed to	be frequently handled or



Features

	 Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP 0EM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
footnotes	 Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard. External power supplies, WWAN modules, power cords, cables and peripherals excluded. 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers. Fiber cushions made from 100% recycled wood fiber and organic materials.

Features

HP Elite SFF 800 G9 Desktop PC

HP Elite SFF 800 G9 Deskt				
Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR® US Federal Energy Management Program (FEMP) EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO Certified China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label Commission Regulation (EC) No 617/2013 (ErP Lot 3)			
Sustainable Impact	Ocean-bound plastic in CPU Fan,	Speaker		
Specifications	 Ocean-bound plastic in CPU Fan, Speaker 60% post-consumer recycled plastic Low halogen Outside Box and corrugated cushions are 100% sustainably sourced and recyclable Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable 			
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the			
Energy Consumption	Desktop model is based on a "Typi	ically Configured Desktop.		
(in accordance with US ENERGY STAR® test method)	115VAC, 60Hz 230VAC, 50Hz 100VAC, 50Hz			
Normal Operation (Short idle)	11.6 W	11.9 W	11.6 W	
Normal Operation (Long idle)	10.4 W	11 W 11 W		
Sleep	0.9 W	0.9 W	0.9 W	
Off	0.7 W	0.7 W	0.6 W	
	NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.			
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	39.672 BTU/hr	40.698 BTU/hr	39.672 BTU/hr	
Normal Operation (Long idle)	35.568 BTU/hr	37.62 BTU/hr	37.62 BTU/hr	
Sleep	3.078 BTU/hr	3.078 BTU/hr	3.078 BTU/hr	
Off	2.394 BTU/hr	2.394 BTU/hr	2.052 BTU/hr	
	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.			
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power Sound Pressure (L _{pAm} , decibels)			
Typically Configured – Idle	3.0		21.3	



Features

Fixed Disk–Random writes		3.3		23.1
Optical Drive – Sequential	3.3		21.8	
reads Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:			
	Spare parts a production.	are available throughout the warranty po	eriod and or for up	to "5" years after the end of
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see 			
	http • Plas ISO	o://www.epeat.net stics parts weighing over 25 grams used 1043. s product is 92.9% recycle-able when pro	in the product are	marked per ISO11469 and
Packaging Materials	External:	PAPER/Corrugated		1158 g
		PAPER/Molded Pulp		590 g
	Internal:	PLASTIC/Polyethylene low density - L		26 g
		packaging material contains at least 0.0		
		ited paper packaging materials contains		-
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.			
	We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve. To obtain a copy of the HP RoHS Compliance Statement, see: HP RoHS position statement.			
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):			
	 Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (BBP) Dibutyl phthalate (DBP) Diisobutyl phthalate (DIBP) 			



Features

	 Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

Features

HP Elite Tower 800 G9 Desktop PC

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR® US Federal Energy Management Program (FEMP) EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO Certified China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label Commission Regulation (EC) No 617/2013 (ErP Lot 3)			
Sustainable Impact Specifications	 Ocean-bound plastic in System at 60% post-consumer recycled pla Low halogen Outside Box and corrugated cush Molded Paper Pulp Cushion inside 	stic ions are 100% sustainably source		
System Configuration	The configuration used for the Ene		ise Emissions data for the	
Energy Consumption (in accordance with US ENERGY STAR® test method)	Desktop model is based on a Typically Configured Desktop. 115VAC, 60Hz 230VAC, 50Hz 100VAC, 60Hz			
Normal Operation (Short idle)	7.4 W	7.5 W	7.2 W	
Normal Operation (Long idle)	2.3 W	2.4 W 2.2 W		
Sleep	2.3 W	2.3 W	2.1 W	
Off	0.6 W	0.7 W 0.5 W		
	NOTE: Energy efficiency data listed is f family. HP computers marked with the Environmental Protection Agency (EPA not offer ENERGY STAR® compliant cor configured PC featuring a hard disk dri system.	ENERGY STAR® Logo are compliant was ENERGY STAR® specifications for configurations, then energy efficiency dave, a high efficiency power supply, and	ith the applicable U.S. mputers. If a model family does ata listed is for a typically d a Microsoft Windows® operating	
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation (Short idle)	25.3 BTU/hr	25.7 BTU/hr	24.6 BTU/hr	
Normal Operation (Long idle)	7.9 BTU/hr	8.2 BTU/hr	7.5 BTU/hr	
Sleep	7.9 BTU/hr	11.6 BTU/hr	7.2 BTU/hr	
Off	2.1 BTU/hr	2.4 BTU/hr	1.7 BTU/hr	
	NOTE: Heat dissipation is calculated be one hour.	ased on the measured watts, assuming	g the service level is attained for	
Declared Noise Emissions	Sound Power Sound Pressure (L _{pAm} , decibels)		Sound Pressure	
(in accordance with ISO 7779 and ISO 9296)	(L _{WAd} , bels)		(L _{pAm} , decibels)	
(in accordance with				



Features

Optical Drive – Sequential reads		3.2		21
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:			
	Spare parts a production.	are available throughout the warranty po	eriod and or for up	to "5" years after the end of
Additional Information	dire	product is in compliance with the Restrictive - 2011/65/EC. HP product is designed to comply with the product is designed to comply with the complex wi		
	(WE	EE) Directive – 2002/96/EC. product is in compliance with California		
	• This	king Water and Toxic Enforcement Act of product is in compliance with the IEEE 1		dard at the Gold level, see
	• Plas	n://www.epeat.net stics parts weighing over 25 grams used	in the product are	marked per ISO11469 and
		1043. product is 93.4% recycle-able when pro	pperly disposed of	at end of life
Packaging Materials	External:	PAPER/Corrugated		1106 g
	_	PAPER/Molded Pulp		666 g
	Internal:	PLASTIC/Polyethylene low density - L		40 g
		packaging material contains at least 0.0		
RoHS Compliance		ted paper packaging materials contains		
nons compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.			
	We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve. To obtain a copy of the HP RoHS Compliance Statement, see: HP RoHS position statement.			
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):			
	 Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (BBP) Dibutyl phthalate (DBP) Diisobutyl phthalate (DIBP) Formaldehyde 			



Features

reatures	
	 Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging
	materials.
	Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Design packaging materials for ease of disassembly.
	Maximize the use of post-consumer recycled content materials in packaging materials.
	Use readily recyclable packaging materials such as paper and corrugated materials.
	 Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible
	manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers . These instructions may be used by recyclers and other WEEE treatment facilities as well as HP 0EM customers who integrate and re-sell HP equipment. Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates:
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842
	and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
footnotes	 Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
	 External power supplies, WWAN modules, power cords, cables and peripherals excluded. 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
	Fiber cushions made from 100% recycled wood fiber and organic materials.

Features

HP Elite Tower 880 G9 Desktop PC

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR® US Federal Energy Management Program (FEMP) EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO Certified China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label Commission Regulation (EC) No 617/2013 (ErP Lot 3)			
Sustainable Impact Specifications	 Ocean-bound plastic in System and CPU Fan, Speaker 60% post-consumer recycled plastic Low halogen Outside Box and corrugated cushions are 100% sustainably sourced and recyclable Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable 			
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a Typically Configured Desktop.			
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz 230VAC, 50Hz 100VAC, 60Hz			
Normal Operation (Short idle)	12.3 W	12.6 W	12.5 W	
Normal Operation (Long idle)	11.4 W	11.1 W 11.4 W		
Sleep	1 W	1 W	0.9 W	
Off	0.6 W	0.7 W	0.6 W	
	NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.			
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation (Short idle)	42.1 BTU/hr	43.1 BTU/hr	42.8 BTU/hr	
Normal Operation (Long idle)	39 BTU/hr	38 BTU/hr	39 BTU/hr	
Sleep	3.4 BTU/hr	11.6 BTU/hr	3.1 BTU/hr	
Off	2.1 BTU/hr 2.4 BTU/hr 2.1 BTU/hr NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.			
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power Sound Pressure (LwAd, bels) (LpAm, decibels)			
Typically Configured – Idle	3.3		21	

Fixed Disk–Random writes		3.4		22
Optical Drive – Sequential reads	4.6		27	
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable			
	features and/or components contained in the product may include:			
	Spare parts a production.	are available throughout the warranty pe	eriod and or for up	to "5" years after the end of
Additional Information		product is in compliance with the Restri	ctions of Hazardo	us Substances (RoHS)
		ctive - 2011/65/EC. HP product is designed to comply with t	he Waste Flectrica	al and Flectronic Fauinment
	(WE	EE) Directive – 2002/96/EC.		
		product is in compliance with California king Water and Toxic Enforcement Act o		ate of California; Safe
		product is in compliance with the IEEE 1		dard at the Gold level, see
	http	://www.epeat.net		
		tics parts weighing over 25 grams used 1043.	in the product are	marked per ISO11469 and
		product is 93.4% recycle-able when pro	perly disposed of	at end of life
		p	perty dispessed of	
Packaging Materials	External:	PAPER/Corrugated		1106 g
		PAPER/Molded Pulp		666 g
	Internal:	PLASTIC/Polyethylene low density - L		40 g
		packaging material contains at least 0.0		
RoHS Compliance		ted paper packaging materials contains lies fully with materials regulations. We		
Kon3 Computance		n the European Union (EU) Restriction of		
		rldwide through the HP GSE. HP has cont		
	legislation in Europe, as well as China, India, and Vietnam.			
	We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical			
	and electronics products.			
	We met our voluntary objective to achieve worldwide compliance with the new EU RoHS			
	requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.			
		opy of the HP RoHS Compliance Stateme	· .	
Material Usage		does not contain any of the following su peral Specification for the Environment a		s ot regulatory limits (refer
	to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):			
	Asbestos Cortain Aza Calaranta			
	 Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics 			me retardants in plastics
	Certain brominated Flame Retail dants – may not be used as flame retail dants in plastics Cadmium			
	Chlorinated Hydrocarbons			
		orinated Paraffins		
		2-Ethylhexyl) phthalate (DEHP)		
		zyl butyl phthalate (BBP) ityl phthalate (DBP)		
	Dibutyl phthalate (DBP)Diisobutyl phthalate (DIBP)			
L		y - p		



	Formaldehyde
	Halogenated Diphenyl Methanes
	Lead carbonates and sulfates
	Lead and Lead compounds
	Mercuric Oxide Batteries
	Nickel – finishes must not be used on the external surface designed to be frequently
	handled or carried by the user.
	Ozone Depleting Substances
	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs)
	Polybrominated Biphenyl Oxides (PBBOs)
	Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT)
	 Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has
	been voluntarily removed from most applications.
	Radioactive Substances
	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging
	materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Design packaging materials for ease of disassembly.
	,
	Maximize the use of post-consumer recycled content materials in packaging materials.
	Use readily recyclable packaging materials such as paper and corrugated materials.
	Reduce size and weight of packages to improve transportation fuel efficiency.
	Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest
	HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	mainer.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for
	each product type for use by treatment facilities. This information (product disassembly
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These
	instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM
	customers who integrate and re-sell HP equipment.
	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842
	and
factuates	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
footnotes	Percentage of ocean-bound plastic contained in each component varies by product Percentage of ocean-bound plastic contained in each component varies by product Percentage of ocean-bound plastic contained in each component varies by product Percentage of ocean-bound plastic contained in each component varies by product
	Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 chandled
	standard.
	External power supplies, WWAN modules, power cords, cables and peripherals excluded. 100% outside and segmented supplies and from supplies and peripherals excluded.
	100% outer box packaging and corrugated cushions made from sustainably sourced cortified and recycled fibers.
	certified and recycled fibers.
	Fiber cushions made from 100% recycled wood fiber and organic materials.

Features

HP EliteOne 840 23.8-inch G9 All-in-One Desktop PC

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR® US Federal Energy Management Program (FEMP) EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO Certified China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label Commission Regulation (EC) No 617/2013 (ErP Lot 3)		
Sustainable Impact Specifications	 Ocean-bound plastic in Rear cover, Speaker Box 65% post-consumer recycled plastic Low halogen Outside Box and corrugated cushions are 100% sustainably sourced and recyclable Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable Bulk packaging available 		
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the All-in-One PC model is based on a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	19.88 W	19.96 W	19.69 W
Normal Operation (Long idle)	2.94 W	3.02 W	2.78 W
Sleep	2.93 W	3.01 W	2.77 W
Off	0.81 W	0.82 W	0.79 W
Una Pinita di A	family. HP computers marked with the Environmental Protection Agency (EP not offer ENERGY STAR® compliant co configured PC featuring a hard disk dr system.	for an ENERGY STAR® compliant produ e ENERGY STAR® Logo are compliant wi A) ENERGY STAR® specifications for cor infigurations, then energy efficiency da ive, a high efficiency power supply, and	ith the applicable U.S. nputers. If a model family does ta listed is for a typically d a Microsoft Windows® operating
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	68 BTU/hr	68.3 BTU/hr	67.3 BTU/hr
Normal Operation (Long idle)	10.1 BTU/hr	10.3 BTU/hr	9.5 BTU/hr
Sleep	10 BTU/hr	10.3 BTU/hr 9.5 BTU	
Off	2.8 BTU/hr 2.8 BTU/hr 2.7 BTU/hr NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)		Sound Pressure (L _{pAm} , decibels)



Typically Configured – Idle		2.6	15.4
Fixed Disk – Random writes		2.6	15.4
Longevity and Upgrading	 6 USB por 2 memory 1 Mini PCI 1 MXM 3.0 1 mSATA 1 2.5" inter 	/or components contained in the prod ts / slots e half-length slot) Type A - 35W slot	
	production.		period and or for up to "5" years after the end of
Additional Information	dire This (WE This Drin This http	ctive - 2011/65/EC. HP product is designed to comply wit EE) Directive - 2002/96/EC. product is in compliance with Califorr king Water and Toxic Enforcement Act product is in compliance with the IEEI://www.epeat.net	1680 (EPEAT) standard at the Gold level, see
			1
Packaging Materials	External:	PAPER/Paper	1240 g
	Intonal	PAPER/Molded Pulp	1489 g
	Internal:	PLASTIC/Other	49 g
		ackaging material contains at least xx ed paper packaging materials contain	
RoHS Compliance	HP Inc. comp restrictions in products won legislation in We believe the elimination of	lies fully with materials regulations. Von the European Union (EU) Restriction of the European Union (EU) Restriction of the Europe, as well as China, India, and Vone RoHS directive and similar laws play of substances of concern. We have sup C, BFRs, and certain phthalates—in fu	Ve were among the first companies to extend the of Hazardous Substances (RoHS) Directive to our ntributed to the development of related
	requirements scope of the evolve.	commitment to include further restric	de compliance with the new EU RoHS July 2013, and we will continue to extend the ted substances as regulations continue to ment, see HP RoHS position statement.
		· · ·	<u> </u>
Material Usage	to the HP Gei	neral Specification for the Environmer	substances in excess of regulatory limits (refer t at ronment/supplychain/gen_specifications.html):
	• Cert	estos ain Azo Colorants ain Brominated Flame Retardants – m	ay not be used as flame retardants in plastics



Features

Features	
	 Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (BBP) Dibutyl phthalate (DBP) Diisobutyl phthalate (DIBP) Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers . These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K

ISO 14001 certificates:

_Certificate.pdf

and

	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf		
HP, Inc. Corporate Environmental	For more information about HP's commitment to the environment:		
Information	Global Citizenship Report		
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications		
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html		
	ISO 14001 certificates:		
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842		
	and		
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf		
footnotes	 Percentage of ocean-bound plastic contained in each component varies by product 		
	 Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard. 		
	 External power supplies, WWAN modules, power cords, cables and peripherals excluded. 		
	 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers. 		
	 Fiber cushions made from 100% recycled wood fiber and organic materials. 		



Features

HP EliteOne 870 27-inch G9 All-in-One Desktop PC

Eco-Label Certifications & declarations	 be labeled with one or more of IT ECO declaration US ENERGY STAR® US Federal Energy Ma 	f these marks: nnagement Progra ed in the United Sta /. vation Program (CE ental Protection A	m (FEMP) ates. See http://w :CP) dministration (SE	the following approvals and may www.epeat.net for registration PA
Sustainable Impact Specifications	Ocean-bound plastic in Rear cover, Speaker Box 70% post-consumer recycled plastic External Power Supply 90% Efficiency Low halogen Outside Box and corrugated cushions are 100% sustainably sourced and recyclable			
System Configuration	 Bulk packaging available The configuration used for the Energy Consumption and Declared Noise Emissions data for the All-in-One PC model is based on a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system. 			
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC	, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	25.79 W	25.88	8 W	25.61 W
Normal Operation (Long idle)	2.99 W	3.08	: W	2.81 W
Sleep	2.96 W	3.05	S W	2.78 W
Off	0.86 W	0.87	' W	0.84 W
Hant Dinging at least	not offer ENERGY STAR® compliar configured PC featuring a hard dis system.	h the ENERGY STAR® (EPA) ENERGY STAR nt configurations, th sk drive, a high effici	PLogo are compliar Specifications for en energy efficiency ency power supply,	nt with the applicable U.S. r computers. If a model family does y data listed is for a typically and a Microsoft Windows® operating
Heat Dissipation*	115VAC, 60Hz	230VAC	, SUHZ	100VAC, 60Hz
Normal Operation (Short idle)	184.2 BTU/hr	184.9 B	TU/hr	182.9 BTU/hr
Normal Operation (Long idle)	21.4 BTU/hr	22 BT		20.1 BTU/hr
Sleep			19.9 BTU/hr	
Off	6.1 BTU/hr 6.2 BTU/hr 6 BTU/hr NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained fone hour.			
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power Sound Pressure (L _{pAm} , decibels)			



Typically Configured – Idle		2.6	15.4	
Fixed Disk – Random writes	2.6			
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:			
	 6 USB ports 2 memory slots 1 Mini PCIe half-length slot 1 MXM 3.0 Type A - 35W slot 1 mSATA slot 1 2.5" internal bay supporting up to Two 2.5" hard drives (HDD/SSD/SED/SSHD) 			
		ternal supporting optical drive are available throughout the warran	ty period and or for up to "5" years after the end o	
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. 			
	 This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). 			
	 This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see http://www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. 			
	• This	product is 97.9% recycle-able when	n properly disposed of at end of life	
Packaging Materials	External:	PAPER/Paper	244 g	
	Internal:	COMPOSITE/paper/carton+plastic PLASTIC/Polyethylene low densit		
	The plastic packaging material contains at least xx% recycled content. The corrugated paper packaging materials contains at least xx% recycled content.			
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.			
	We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.			
	We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.			
	To obtain a copy of the HP RoHS Compliance Statement, see: HP RoHS position statement.			
Material Usage	to the HP Ge	neral Specification for the Environm	ng substances in excess of regulatory limits (referent at experience) wironment/supplychain/gen_specifications.html):	



reatures	
	 Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (BBP) Dibutyl phthalate (DBP) Diisobutyl phthalate (DIBP) Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate Environmental Information	For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications

	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
footnotes	 Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard. External power supplies, WWAN modules, power cords, cables and peripherals excluded. 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.



Features

SERVICE AND SUPPORT

On-site Warranty¹: One-year (1-1-1) limited warranty delivers one year of on-site, next business day² service for parts and labor support. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/qo/cpc.³

- 1. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 2. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
- 3. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

CERTIFICATION AND COMPLIANCE

Energy Efficiency Compliance

ENERGY STAR® certified. EPEAT® registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018.



Technical Specifications – Processors

PROCESSORS

12th Generation Intel® Core™ Processors

All HP EliteDesk 800 G9 Business PC models featuring this technology include processors that are part of the Intel® Stable Image Platform Program (SIPP) designed to ensure the stability promise inherent in the value proposition of the HP Elite series G9 Desktop Business PC.

Intel® Management Engine (ME) v16 – An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 16 includes the following advanced management functions:

- Support for configuration of Intel ME 16.0 capabilities
- No reset after provisioning
- Support for Intel Enterprise Digital Fence
- The Platform Discovery Utility can now discover these additional Intel products:
 - o Public Key Infrastructure
- Profile Editor and Profile Editor Plugin Interface
- Required Permissions for Solutions Framework





Technical Specifications – Display Panel Specifications

DISPLAY PANEL SPECIFICATIONS

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower. For All in One only Intel® HD Graphics (integrated).

23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) Projected Capacitive Touch supports up to 10 touch-points

Support HW low blue light feature

 Typo
 IPS WLED Backlit LCD

 Active area (mm)
 527.04 x 296.46

 Native resolution (HxV)
 1920 x 1080

 Refresh rate
 60 Hz @ 1920 x 1080

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.2745 x 0.2745

Contrast ratio 1000:1
Brightness 300nits*
Viewing angle (HxV) 178° x 178°

Backlight lamp life (to half brightness) 30,000 hours minimum

Color support Up to 16.7 million colors with 8 Bit(6 Bit + FRC)

Color gamutsRGB 99%Anti-glareYesResponse time14ms

Default color temperature Warm (6500K)

NOTE*: Actual brightness will be lower with touchscreen

23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) non-touch

Support HW low blue light feature

 Type
 IPS WLED Backlit LCD

 Active area (mm)
 527.04 x 296.46

 Native resolution (HxV)
 1920 x 1080

 Refresh rate
 60 Hz @ 1920 x 1080

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.2745 x 0.2745

Contrast ratio 1000:1
Brightness 250nits*
Viewing angle (HxV) 178° x 178°

Backlight lamp life (to half brightness) 30,000 hours minimum

Color support Up to 16.7 million colors with 8 Bit(6 Bit + FRC)

Color gamutNTSC 72%Anti-glareYesResponse time14ms

Default color temperature Warm (6500K)



Technical Specifications – Display Panel Specifications

27.0" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) non-touch

Support HW low blue light feature

 Type
 IPS WLED Backlit LCD

 Active area (mm)
 597.888 x 336.312

 Native resolution (HxV)
 1920 x 1080

 Refresh rate
 60 Hz @ 1920 x 1080

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.3114 x 0.3114

Contrast ratio1000:1Brightness250nits*Viewing angle (HxV)178° x 178°

Backlight lamp life (to half brightness) 30,000 hours minimum

Color support Up to 16.7 million colors with 8 Bit(6 Bit + FRC)

Color gamutNTSC 72%Anti-glareYesResponse time14ms

Default color temperature Warm (6500K)

NOTE*: Actual brightness will be lower with touchscreen

27.0" diagonal IPS widescreen WLED backlit anti-glare LCD (2560 x 1440) non-touch or optional Projected Capacitive Touch supports up to 10 touch-points

Support HW low blue light feature

TypeIPS WLED Backlit LCDActive area (mm)596.736 x 335.664Native resolution (HxV)2560 x 1440

Refresh rate 60 Hz @ 2560 x 1440

Aspect ratio 16:9

Pixel pitch (HxV)(mm) 0.2331 x 0.2331

Contrast ratio1000:1Brightness*250nits*Viewing angle (HxV)178° x 178°

Backlight lamp life (to half brightness) 30,000 hours minimum

Color support Up to 16.7 million colors with 8 bit (True)

Color gamutNTSC 72%Anti-glareYesResponse time14ms

Default color temperature Warm (6500K)

NOTE*: Actual brightness will be lower with touchscreen



Technical Specifications – Display Panel Specifications

Height - Vertical/Landscape Adjustment	130mm (±2 mm)	
Portrait Adjustment	No portrait	
Tilt Angle	-5° to +18° (±2°) in landscape and portrait	
Rotation (Swivel)	90° (±1°) (45 left, 45 right)	
Pivot	No pivot	
Height - Vertical Adjustment	No height	
Tilt Angle	+36.5° to +58° (+/-1.5°)	
Rotation (swivel)	No swivel	
	Portrait Adjustment Tilt Angle Rotation (Swivel) Pivot Height - Vertical Adjustment Tilt Angle	



Technical Specifications – Graphics

GRAPHICS

HP Elite Mini 800 G9 Desktop PC

Intel® HD Graphics (integrated)

VGA Controller Integrated

DisplayPort™ Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-

Stream Technology for a maximum of 3 displays connected to any output controlled by Intel®

Graphics

HDMI (optional) Supports HDMI 2.1 features

Supports HDCP 2.3

Supports audio over HDMI

VGA (optional) VGA output

USB-C® DP Alt Mode (optional) DisplayPort™ over the optional USB-C® module

Memory The actual amount of maximum graphics memory can be >4GB. System memory is allocated

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an

optimal balance between graphics and system memory use.

Maximum Color Depth up to 16 bits/color

Graphics/Video API Support HEVC 10b Enc/12b Dec HW

VP9 12b Dec HW

HDR Rec. 2020 DX12

 Max resolution (VGA)
 2048 x 1536@60Hz

 Max resolution (DP)
 4096 x 2160@60Hz

 Max resolution (HDMI)
 4096 x 2160@60Hz

 Max resolution (option VGA)
 2048x1536p, 60Hz

 Max resolution (option DP)
 5120x2160p, 60Hz

 Max resolution (option HDMI)
 3840x2160p, 60Hz

NVIDIA® GeForce 3050Ti Graphics Card

Engine Clock 735 MHz
Memory Clock 5501 MHz
Memory Size (width) 4GB (128-bit)
Memory Type GDDR6

Max. Resolution (DP) 5120x3200@60Hz

HDCP Compliance Yes **Total power consumption (W)** 35W

Technical Specifications – Graphics

HP Elite SFF 800 G9 Desktop PC

Intel® HD Graphics (integrated)

VGA Controller Integrated

DisplayPort™ Multimode capable; supports HDCP, Display Port Audio (2 streams), Onboard support HBR2

link rates/option DP support to HBR3 and Multi-Stream Technology for a maximum of 4

displays connected to any output controlled by Intel® Graphics

HDMI (onboard / optional) Supports HDMI 2.1 features (onboard HDMI support HDMI1.4; Option HDMI support HDMI

2.1)

Supports HDCP 2.3 (Support HDCP 1.4/2.3)

Supports audio over HDMI

VGA (optional)

VGA output

USB-C® DP Alt Mode (optional) DisplayPort™ over the optional USB-C® module (Support DP1.4 HBR2)

The actual amount of maximum graphics memory can be >4GB. System memory is Memory

allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT),

to provide an optimal balance between graphics and system memory use.

Maximum Color Depth up to 16 bits/color

Graphics/Video API Support HEVC 10b Enc/12b Dec HW

VP9 12b Dec HW à AV1 decode support 8/10b, 4:2:0

HDR Rec. 2020 DX12

Max. Resolution (VGA Option) 2048 x 1536@60Hz Max. Resolution (Onboard HDMI) 1920 x 1080@60Hz Max. Resolution (Option HDMI) 3840 x 2160@60Hz Max. Resolution (On board DP) 3840 x 2160@60Hz Max. Resolution (Option DP) 5120 x 2280@60Hz

NVIDIA® T400 2GB Graphics Card

Engine Clock 2100 MHz **Memory Clock** 5001 MHz **Memory Size (width)** 2GB (64-bit) **Memory Type** 256M x 16 GDDR6 Max. Resolution (DP) 7680x4320@120Hz

Multi Display Support 4 displays **HDCP Compliance** Yes Rear I/O connectors (bracket) mDPx3

Cooling (active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) 30W

PCB form-factor with bracket LP PCB with LP bracket



Technical Specifications – Graphics

NVIDIA® T400 4GB Graphics Card

Engine Clock 2100 MHz **Memory Clock** 5001 MHz Memory Size (width) 4GB (64-bit) 512M x 16 GDDR6 **Memory Type** Max. Resolution (DP) 7680x4320@120Hz

Multi Display Support 4 displays

HDCP Compliance Yes Rear I/O connectors (bracket) mDPx3

Cooling (active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) 30W

PCB form-factor with bracket LP PCB with LP bracket

HP Elite Tower 800 G9 Desktop PC

Intel® UHD Graphics (integrated)

VGA Controller Integrated

DisplayPort™ Multimode capable; supports HDCP, Display Port Audio (2 streams), Onboard support HBR2

link rates/option DP support to HBR3 and Multi-Stream Technology for a maximum of 4

displays connected to any output controlled by Intel® Graphics

HDMI (onboard / optional) Supports HDMI 2.1 features (onboard HDMI support HDMI1.4; Option HDMI support HDMI 2.1)

Supports HDCP 2.3 (Support HDCP 1.4/2.3)

Supports audio over HDMI

VGA (optional)

USB-C® DP Alt Mode (optional)

DisplayPort™ over the optional USB-C® module (Support DP1.4 HBR2)

The actual amount of maximum graphics memory can be >4GB. System memory is allocated Memory

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an

optimal balance between graphics and system memory use.

Maximum Color Depth

Graphics/Video API Support

HEVC 10b Enc/12b Dec HW

VP9 12b Dec HW à AV1 decode support 8/10b, 4:2:0

HDR Rec. 2020 DX12

VGA output

Max. Resolution (VGA Option)

Max. Resolution (Onboard

HDMI)

2048 x 1536@60Hz 1920 x 1080@60Hz

up to 16 bits/color

3840 x 2160@60Hz

Max. Resolution (Option

HDMI)

Max. Resolution (Option HDMI) 3840 x 2160@60Hz Max. Resolution (On board DP) 3840 x 2160@60Hz Max. Resolution (Option DP) 5120 x 2280@60Hz



Technical Specifications – Graphics

NVIDIA® GeForce® RTX 3070 LHR Graphics Card

 Engine Clock
 1730 MHz

 Memory Clock
 8000 MHz

 Memory Size(width)
 8 GB (256-bit)

 Memory Type
 256M x 32 GDDR6

 Max. Resolution (HDMI)
 7680x4320@60Hz

 Max. Resolution (DP)
 7680x4320@60Hz

Multi Display Support 4 displays

HDCP Compliance Yes

Rear I/O connectors (bracket) HDMIx1+ DPx3

Cooling (active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) <220W

PCB form-factor with bracket ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® GeForce® RTX 3060 LHR Graphics Card

Engine Clock Base: 1320 Mhz Boost: 1777 Mhz

Frame Buffer Size / Width 12GB / 192bit

Graphic Memory Type / Clock 512Mx16 GDDR6 @ 6 pcs / 16Gbps

 Max. Resolution (HDMI)
 7680x4320@60Hz

 Max. Resolution (DP)
 7680x4320@60Hz

Multi Display Support 4 displays

HDCP Compliance Yes

Rear I/O connectors (bracket) HDMIx1+ DPx3

Cooling (active/passive) Active fansink with 4 pin fan control

Total power consumption (W) 170W

PCB form-factor with bracket ATX (X:188mm/Y:111.15mm/Z: 34.80mm) PCB with ATX dual slot bracket

NVIDIA® T400 2GB Graphics Card

Engine Clock2100 MHzMemory Clock5001 MHzMemory Size (width)2GB (64-bit)Memory Type256M x 16 GDDR6Max. Resolution (DP)7680x4320@120Hz

Multi Display Support4 displaysHDCP ComplianceYesRear I/O connectors (bracket)mDPx3

Cooling (active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) 30W



Technical Specifications – Graphics

NVIDIA® T400 4GB Graphics Card

Engine Clock2100 MHzMemory Clock5001 MHzMemory Size (width)4GB (64-bit)Memory Type512M x 16 G

 Memory Type
 512M x 16 GDDR6

 Max. Resolution (DP)
 7680x4320@120Hz

Multi Display Support4 displaysHDCP ComplianceYesRear I/O connectors (bracket)mDPx3

Cooling (active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption (W) 30W

PCB form-factor with bracket LP PCB with LP bracket



Technical Specifications – Graphics

HP EliteOne 840 23.8 inch G9 All-in-One Desktop PC

Intel® UHD Graphics (integrated)

VGA Controller Integrated

DisplayPort™ 1.4 Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR3 link rates and Multi-

Stream Technology for a maximum of 3 displays (including the integrated panel and all

attached displays)

HDMI-in Support HDMI-In

Memory The actual amount of maximum graphics memory can be >4GB. System memory is allocated

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an

optimal balance between graphics and system memory use.

Maximum Color Depth Graphics/Video API Support up to 10 bits/color HEVC 10b Enc/Dec HW

VP9 10b Dec HW

HDR Rec. 2020 DX12

 Max. Resolution (VGA)
 2048 x 1536@60Hz

 Max. Resolution (HDMI)
 4096 x 2160@60Hz

 Max. Resolution (DP)
 4096 x 2160@60Hz

NVIDIA® GeForce 3050Ti Graphics Card

Engine Clock 735 MHz
Memory Clock 5501 MHz
Memory Size (width) 4GB (128-bit)
Memory Type GDDR6

Max. Resolution (DP) 5120x3200@60Hz

HDCP Compliance Yes
Total power consumption (W) 35W



Technical Specifications – Graphics

HP EliteOne 870 27 inch G9 All-in-One Desktop PC

Intel® UHD Graphics (integrated)

VGA Controller Integrated

DisplayPort™ 1.4 Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR3link rates and Multi-

Stream Technology for a maximum of 3 displays (including the integrated panel and all

attached displays)
Support HDMI-In

Memory The actual amount of maximum graphics memory can be >4GB. System memory is allocated

for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an

optimal balance between graphics and system memory use.

Maximum Color Depth Graphics/Video API Support

HDMI-in

up to 10 bits/color HEVC 10b Enc/Dec HW

VP9 10b Dec HW

HDR Rec. 2020 DX12

 Max. Resolution (VGA)
 2048 x 1536@60Hz

 Max. Resolution (HDMI)
 4096 x 2160@60Hz

 Max. Resolution (DP)
 4096 x 2160@60Hz

NVIDIA® GeForce 3050Ti Graphics Card

Engine Clock 735 MHz

Memory Clock 5501 MHz

Memory Size (width) 4GB (128-bit)

Memory Type GDDR6

Max. Resolution (DP) 5120x3200@60Hz

HDCP Compliance Yes
Total power consumption (W) 35W



Technical Specifications – Storage

STORAGE

500GB 7200RPM 3.5in SATA HDD

Capacity500 GBRotational Speed7,200 rpmInterfaceSATA 6.0 Gb/s

Buffer Size32 MBLogical Blocks976,773,168Seek Time11 ms (Average)Height1 in/2.54 cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

1TB 7200RPM 3.5in SATA HDD

Capacity1 TBRotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer Size64 MB

 Logical Blocks
 1,953,525,168

 Seek Time
 11 ms (Average)

 Height
 1 in/2.54 cm

Width (nominal) Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

2TB 7200RPM 3.5in SATA HDD

Capacity 2 TB

Rotational Speed 7,200 rpm

Interface SATA 6 Gb/s

Buffer Size 128 MB

Logical Blocks 3,907,050,33

 Logical Blocks
 3,907,050,336

 Seek Time
 11 ms (Average)

 Height
 1.028 in/26.11 mm

Width (nominal) Media diameter: 3.5 in/88.9 mm

Physical size: 4 in/102 mm

Operating Temperature 41° to 131° F (5° to 55° C)



Technical Specifications – Storage

500GB 7200RPM 2.5in SATA HDD

Capacity 500 GB

Rotational Speed 7,200 rpm

Interface SATA 6 Gb/s

Buffer Size Up to 128 MB

Logical Blocks 976,773,168

Seek Time 12 ms (Average)

Height 0.283 in/7.2 mm (Max.)

 Height
 0.283 in/7.2 mm (Max.)

 Width (nominal)
 2.75 in/70 mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

1TB 7200RPM 2.5in SATA HDD

Capacity 1 TB **Rotational Speed** 7,200 rpm Interface SATA 6 Gb/s **Buffer Size** Up to 128 MB **Logical Blocks** 1,953,525,168 **Seek Time** 12 ms (Average) 0.283 in/7.2 mm (Max.) Height Width (nominal) 2.75 in/70 mm (nominal) 41° to 131° F (5° to 55° C) **Operating Temperature**

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

2TB 5400RPM 2.5in SATA HDD

Capacity 2 TB

Rotational Speed 5,400 rpm

Interface SATA 6 Gb/s

Buffer Size 128 MB

Logical Blocks 3,907,050,336

Seek Time 12 ms (Average)

Height0.374 in/9.5 mm (nominal)Width (nominal)2.75 in/70 mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)



Technical Specifications – Storage

500GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD

Capacity 500 GB

Architecture Self-Encrypting (SED) Solid State Drive with SATA interface

 Interface
 SATA 6 Gb/s

 Buffer Size
 128 MB

 Logical Blocks
 976,773,168

 Seek Time
 12 ms (Average)

 Height
 0.283 in/7.2 mm (Max.)

 Width
 2.75 in/70 mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

256GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10a 256 GB Capacity Height 2.3 mm Length 80 mm Width 22 mm PCIe NVMe Interface **Maximum Sequential Read** 3200 MB/s ±20% **Maximum Sequential Write** 2000 MB/s ±20% **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; L1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

512GB M.2 2280 PCIe NVMe SSD

Drive Weight< 10g</td>Capacity512 GBHeight2.3 mmLength80 mmWidth22 mmInterfacePCIe NVMeMaximum Sequential Read3200 MB/s

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM: L1.2



Technical Specifications – Storage

1TB M.2 2280 PCIe NVMe SSD

Drive Weight < 10g
Capacity 1 TB
Height 2.3 mm
Length 80 mm
Width 22 mm
Interface PCIe NVMe

 Maximum Sequential Read
 3200 MB/s ±20%

 Maximum Sequential Write
 3200 MB/s ±20%

 Logical Blocks
 2,000,409,264

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; L1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10q 256 GB Capacity 2.3 mm Height Length 80 mm Width 22 mm **Interface** PCIE Gen4x4 **Maximum Sequential Read** 4000 MB/s ±20% **Maximum Sequential Write** 2000 MB/s ±20% **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; L1.2; Pyrite 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

< 10g **Drive Weight** Capacity 512 GB Height 2.3 mm Length 80 mm Width 22 mm PCIE Gen4x4 Interface **Maximum Sequential Read** 6400 MB/s ±20% **Maximum Sequential Write** 3500 MB/s ±20% **Logical Blocks** 1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; L1.2; Pyrite 2.0



Technical Specifications – Storage

1TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10q Capacity 1 TB Height 2.3 mm Length 80 mm Width 22 mm Interface PCIE Gen4x4 Maximum Sequential Read 6400 MB/s ±20% **Maximum Sequential Write** 5000 MB/s ±20% Logical Blocks 2.000.409.264

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; L1.2; Pyrite 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

2TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10q 2 TB Capacity 2.3 mm Height Length 80 mm Width 22 mm **Interface** PCIE Gen4x4 **Maximum Sequential Read** 6400 MB/s ±20% **Maximum Sequential Write** 5000 MB/s ±20% **Logical Blocks** 4,000,797,360

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; L1.2; Pyrite 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

< 10g **Drive Weight** 256 GB Capacity Height 2.3 mm Length 80 mm Width 22 mm PCIE Gen4x4 Interface **Maximum Sequential Read** 4000 MB/s ±20% **Maximum Sequential Write** 2000 MB/s ±20% **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; L1.2; TCG Opal 2.0



Technical Specifications – Storage

512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight < 10q Capacity 512 GB Height 2.3 mm Length 80 mm Width 22 mm Interface PCIE Gen4x4 Maximum Sequential Read 6400 MB/s ±20% **Maximum Sequential Write** 3500 MB/s ±20%

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

1.000.215.216

Features TRIM; L1.2; TCG Opal 2.0

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

OPTICAL DISC DRIVES

Logical Blocks

HP 9.5mm Slim DVD-ROM Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) Up to 0.31 lb (140q) without bezel

Read Speeds DVD+R/-R/+RW/

> -RW/+R DL /-R DL Up to 8X DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

Access time

(typical reads, including

settling)

Random: DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full stroke: DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

Source Slimline SATA DC power receptacle **Power**

> DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Environmental conditions Temperature 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80% (operating - non-condensing)

Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim DVD Writer Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc recording capacity Up to 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.31 lb (140 g) **Write Speeds** DVD-R DL - Up to 6X DVD+R - Up to 8X



Technical Specifications – Storage

DVD+RW - Up to 8X DVD+R DL - Up to 6X DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X

DVD-RW, DVD+RW - Up to 8X

Read Speeds DVD-R DL, DVD+R DL - Up to 8X

DVD+R, DVD-R - Up to 8X

DVD-ROM DL, DVD-ROM - Up to 8X

CD-ROM, CD-R - Up to 24X

CD-RW - Up to 24X

Access time

(typical reads, including

Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)

settling)

See Silville SATA DS

Power Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical)

Environmental conditions (operating - non-condensing)

Temperature 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)





Technical Specifications – Networking

NETWORKING AND COMMUNICATIONS

Intel® I219-LM 1 Gigabit	Network Connection LOM (vPro)
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection)
IEEE Compliance	Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling (Hash Mode Only) Jumbo Frame 9K
Power consumption	Cable Disconnetion: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
Power	ACPI compliant – multiple power modes
Management	Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel® I225-LM 2.5 Gigabit Network Connection LOM (non-vPro)	
Connector	RJ-45
System Interface	PCI(Intel proprietary) + SMBus
Data rates supported	1. 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
	2. 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
	3. 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40)
	4. 2.5 Gbit/s operation (2.5GBASE-T; IEEE 802.3bz Clause 126)
	5. Auto-Negotiation (Automatic Speed Selection)
	Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 & 1000 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support
-	IEEE 802.1q VLAN support
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)
	IEEE 802.3az EEE (Energy Efficient Ethernet)
	IEEE 802.3i 10BASE-T
	IEEE 802.3u 100BASE-TX
	IEEE 802.3ab 1000BAE-T
	IEEE 802.3bz 2.5GBASE-T



Performance	TCP/IP/UDP Checksum Offload (configurable)
i ciroimance	Protocol Offload (ARP & NS)
	Large send offload and Giant send offload
	Receiving Side Scaling (Hash Mode Only)
	Jumbo Frame 9K
Da	
Power consumption	Cable Disconnetion: 25mW
	100Mbps Full Run: 450mW
	1000bp Full Run: 1000mW
	WoL Enable(S3/S4/S5): 50mW
	WoL Disable(S3/S4/S5): 25mW
Power	ACPI compliant – multiple power modes
Management	Situation-sensitive features reduce power consumption
	Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame);
	Wake-on-LAN from off (Magic Packet only)
	PXE 2.1 Remote Boot
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))
	Comprehensive diagnostic and configuration software suite
	Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel® non-vPro™ support with appropriate Intel® chipset components



Realtek RTL8852BE 802.1	1ax 2x2 Wi-Fi + BT5.2 (802.11ax 2x2, supporting gigabit data rate)¹
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11ax
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi certified modules
Frequency Band	802.11b/g/n/ax
	• 2.402 – 2.482 GHz
	802.11a/n/ac/ax
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: max 300Mbps
	• 802.11ac: max 866.7Mbps
	• 802.11ax: max 1201Mbps
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security ²	• IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only
	AES-CCMP: 128 bit in hardware
	802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	WPA3 certification
	• IEEE 802.11i
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	
	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ³	• 802.11b: +18.5dBm minimum
•	• 802.11g: +17.5dBm minimum
	• 802.11a: +18.5dBm minimum
	• 802.11n HT20(2.4GHz): +15.5dBm minimum
	• 802.11n HT40(2.4GHz): +14.5dBm minimum
	• 802.11n HT20(5GHz): +15.5dBm minimum
	• 802.11n HT40(5GHz): +14.5dBm minimum
	• 802.11ac VHT80(5GHz): +11.5dBm minimum
	• 802.11ax HE40(2.4GHz): +10dBm minimum
	802.11ax HE80(5GHz): +10dBm minimum
Power Consumption	• Transmit mode:2.5 W
	• Receive mode:2 W



	• Idle mode (PSP): 180 mW (WLAN Associated)
	• Idle mode: 50 mW (WLAN unassociated)
	Connected Standby/Modern Standby: 10mW Partial Standby Agents
Daway Managament	Radio disabled: 8 mW ACRI and BCI Frances compliant across separate.
Power Management	ACPI and PCI Express compliant power management
Danaissay Camaisississa	802.11 compliant power saving mode
Receiver Sensitivity ⁴	802.11b, 1Mbps: -93.5dBm maximum
	802.11b, 11Mbps: -84dBm maximum
	802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum
	802.11n, MCS07: -67dBm maximum
	802.11n, MCS0767dBiri maximum
	802.11ac, MCS0: -84dBm maximum
	802.11ac, MCS9: -59dBm maximum
	•802.11ax, MCS11(HE40): -57dBm maximum
	•802.11ax, MCS11(HE80): -54dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure
Antenna type	Thigh efficiency afficinia with spatial diversity, mounted in the display efficiosare
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN
	MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm
Dimensions	2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8g
	2. Type 126: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C)
remperature	Non-operating: -40° to 176° F (-40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing)
	Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m)
	Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF:
•	LED OFF – Radio ON
HP Integrated Module with Bl	uetooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1 Compliant/5.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)
inamoer of fivalitable chamicis	BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	
bata kates and Timougnput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or
	864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum
	transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW
	Peak (Rx): 230 mW
	Selective Suspend: 17 mW
Electrical Interface	Microsoft Windows Bluetooth Software
Bluetooth® Software Supported	Microsoft Windows ACPI, and USB Bus Support



Link Topology	
Power Management	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Certifications	ETS 300 328, ETS 300 826
	Low Voltage Directive IECOEO
	Low Voltage Directive IEC950
	UL, CSA, and CE Mark
	Peak (Tx): 330 mW
	Peak (Rx): 230 mW
	Selective Suspend: 17 mW
Power Management	Microsoft Windows Bluetooth Software
Certifications	
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance
	LE Link Layer Ping
	LE Dual Mode
	LE Link Layer
	LE Low Duty Cycle Directed Advertising
	LE L2CAP Connection Oriented Channels
	Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full
	LE Privacy 1.2 –Link Layer Privacy
	LE Privacy 1.2 –Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP)
	Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)
	BT5.1
	ESR9/10 Compliance
	LE Advertisement Extensions
	Channel Selection Algo
	Limited High Duty Cycle Non-Connectable Advertising
	2Mbps LE
	LE Long Range

^{1.} Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.



^{2.} Check latest software/driver release for updates on supported security features.

^{3.} The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

^{4.} Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Technical Specifications – Networking and Communications

Intel AX211 Wi_Fi 6F +RT 5 2	M.2 160MHz CNVi WW WLAN¹
Wireless LAN Standards	IEEE 802.11a
Wiletess EMN Stallaal as	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11ax
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n/ax
	• 2.402 – 2.482 GHz
	802.11a/n/ac/ax
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
	• 5.955 – 6.415 GHz
	• 6.435 – 6.515 GHz
	• 6.535 – 6.875 GHz
	• 6.895 – 7.115 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
Data Nates	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: max 300Mbps
	• 802.11ac: 1733Mbps
	• 802.11ax: max 2.4Gbps
Modulation	Direct Sequence Spread Spectrum
rioudation	bliect Sequence Spread Spectrum
	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	, 1024QAM
Security ²	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
Security-	AES-CCMP: 128 bit in hardware
	802.1x authentication WPA WPA2 902.1x WPA PSK WPA2 PSK TKIP and ASS
	WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2
	WPA2 certification
	WPA3 certification
	• IEEE 802.11i
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	
	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ³	• 802.11b: +17dBm minimum
	• 802.11g: +16dBm minimum
	• 802.11a: +17dBm minimum
	• 802.11n HT20(2.4GHz): +14dBm minimum
	• 802.11n HT40(2.4GHz): +13dBm minimum



Technical Specifications – Networking and Communications

	• 802.11n HT40(5GHz): +13dBm minimum
	• 802.11ac VHT80(5GHz): +10dBm minimum
	802.11ac VHT160(5GHz): +10dBm minimum
	• 802.11ax HE40(2.4GHz): +12dBm minimum
	• 802.11ax HE80(5GHz): +10dBm minimum
De la Caraciana de la caracian	• 802.11ax HE160(5GHz): +10dBm minimum
Power Consumption	• Transmit mode 2.0 W
	Receive mode 1.6 W
	- Neceive mode 1.0 W
	• Idle mode (PSP) 180 mW (WLAN Associated)
	fate mode (i 51) 100 mm (WEMM issociated)
	Idle mode 50 mW (WLAN unassociated)
	,
	Connected Standby 10mW
	Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management
	802.11 compliant power saving mode
Receiver Sensitivity ⁴	•802.11b, 1Mbps: -93.5dBm maximum
	•802.11b, 11Mbps: -84dBm maximum
	• 802.11a/g, 6Mbps: -86dBm maximum
	• 802.11a/g, 54Mbps: -72dBm maximum
	• 802.11n, MCS07: -67dBm maximum
	• 802.11n, MCS15: -64dBm maximum
	• 802.11ac, MCS0(VHT80): -84dBm maximum
	• 802.11ac, MCS9(VHT80): -59dBm maximum
	• 802.11ac, MCS9(VHT160): -58.5dBm maximum
	•802.11ax, MCS11(HE40): -57dBm maximum
	•802.11ax, MCS11(HE80): -54dBm maximum
Antenna type	•802.11ax, MCS11(HE160): -53.5dBm maximum High efficiency antenna with spatial diversity, mounted in the display enclosure
Antenna type	I fight efficiency affering with spatial diversity, mounted in the display efficiosure
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN
	MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm
	2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8g
3	2. Type 1216: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C)
<u> </u>	Non-operating: –40° to 176° F (–40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing)
	Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m)
	Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
HP Integrated Module with Blud	etooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1/5.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)
number of Available Chaimels	BLE: 0~39 (2 MHz/CH)
Data Pates and Throughout	
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps



	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth [®] Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826
	Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection - Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.2 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range

^{1.} Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.



^{2.} Check latest software/driver release for updates on supported security features.

^{3.} The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

^{4.} Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Intel AX211 Wi-Fi 6F +RT 5.	2 M.2 vPro 160MHz CNVi WW WLAN¹
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11ax
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n/ax
	• 2.402 – 2.482 GHz
	802.11a/n/ac/ax
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
	• 5.955 – 6.415 GHz
	• 6.435 – 6.515 GHz
	• 6.535 – 6.875 GHz
	• 6.895 – 7.115 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: max 300Mbps
	• 802.11ac: 1733Mbps
	• 802.11ax: max 2.4Gbps
Modulation	Direct Sequence Spread Spectrum
	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	, 1024QAM
Security ²	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
-	AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	WPA3 certification
	• IEEE 802.11i
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	
	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ³	• 802.11b: +17dBm minimum
-	• 802.11g: +16dBm minimum
	• 802.11a: +17dBm minimum
	• 802.11n HT20(2.4GHz): +14dBm minimum
	• 802.11n HT40(2.4GHz): +13dBm minimum
	• 802.11n HT20(5GHz): +14dBm minimum



	• 802.11n HT40(5GHz): +13dBm minimum
	• 802.11ac VHT80(5GHz): +10dBm minimum
	• 802.11ac VHT160(5GHz): +10dBm minimum
	• 802.11ax HE40(2.4GHz): +12dBm minimum
	• 802.11ax HE80(5GHz): +10dBm minimum
	• 802.11ax HE160(5GHz): +10dBm minimum
Power Consumption	• Transmit mode 2.0 W
	. Deserve mede 1 CM
	Receive mode 1.6 W
	• Idle mode (PSP) 180 mW (WLAN Associated)
	Tate mode (1 31) 100 mw (WEAR A330clated)
	• Idle mode 50 mW (WLAN unassociated)
	, , , , , , , , , , , , , , , , , , , ,
	Connected Standby 10mW
	Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management
	802.11 compliant power saving mode
Receiver Sensitivity ⁴	•802.11b, 1Mbps: -93.5dBm maximum
	•802.11b, 11Mbps: -84dBm maximum
	• 802.11a/g, 6Mbps: -86dBm maximum
	• 802.11a/g, 54Mbps: -72dBm maximum
	• 802.11n, MCS07: -67dBm maximum
	• 802.11n, MCS15: -64dBm maximum
	• 802.11ac, MCS0(VHT80): -84dBm maximum
	• 802.11ac, MCS9(VHT80): -59dBm maximum
	• 802.11ac, MCS9(VHT160): -58.5dBm maximum
	•802.11ax, MCS11(HE40): -57dBm maximum
	•802.11ax, MCS11(HE80): -54dBm maximum
	•802.11ax, MCS11(HE160): -53.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure
	The such added disable and 2.4/5 CHz automore are availed to the soud to assess that AN
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	
Dimensions	PCI-Express M.2 MiniCard 1. Type 2230: 2.3 x 22.0 x 30.0 mm
Dillielisiolis	2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8g
weight	2. Type 1216: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (–10° to 70° C)
i emperature	Non-operating: –40° to 176° F (–40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing)
numunty	Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m)
ntituue	Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON
HP Integrated Module with Blu	etooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology
Bluetooth [®] Specification	4.0/4.1/4.2/5.0/5.1/5.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)
	BLE: 0~39 (2 MHz/CH)
	1 - 20 /



Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW
	Peak (Rx): 230 mW
	Selective Suspend: 17 mW
Bluetooth° Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826
	Low Voltage Directive IEC950
	UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 - Link Layer Privacy LE Privacy 1.2 - Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.2 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE

^{1.} Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

^{4.} Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/q (OFDM modulation).



^{2.} Check latest software/driver release for updates on supported security features.
3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

HP Flex 1GbE Fiber LC Sir	gle Port
Connector	Fiber
Cabling	I GbE over Category OM1 (or better) up to 100m
Controller	Microchip LAN7801
Data Rates Supported	100/1000 Mbps
Compliance	IEE 802.1q priority enconding/tagging (QoS, CoS)
	IEE 802.1q VLAN tagging
	IEE 802.3x flow control
Bus Architecture	USB
Power requirement	Requires 3.3V (Integrated regulators for code Vdc)
Boot ROM support	Yes
Network transfer mode	Full-duplex; Half duplex
Network transfer rate	100BASE-X (Half-duplex) 100Mbps
	1000BASE-X (Half-duplex) 1000Mbps
	1000BASE-X (Full-duplex) 2000Mbps
Operating temperature	32° to 95° F (0° to 35°C)
calvin	1.5 x 1.7 x 0.75 in (3.84 x 4.3 x 1.9 cm)
Operating System Driver	Windows 11 64-Bit
Support	Windows 10 64-Bit
	Linux [®]



Technical Specifications – Input/Output Devices

I/O DEVICES

Physical Characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)		
	Dimensions (L x W x H)	171.97 x 68.35 x 8.27 in (436.8± 1.5 x 137.6± 1.0 x 21.0± 1.0 cm)		
	Weight	1.32 lb (0.6± 0.08 kg)		
Electrical	Operating voltage	4.4-5.25VDC		
	Power consumption	50-mA maximum (with 5 VDC power supplied and three LEDs ON)/		
	System interface	USB or PS/2		
	ESD	Contact Discharge: 2, 4,6,8KV Air Discharge: 2, 4, 8,10,12.5KV		
	EMI - RFI	Conforms to FCC rules for a Class B computing device		
Mechanical	Keycaps	Low-profile design		
	Switch actuation	60±12.5g nominal peak force with tactile feedback		
	Switch life	10 million keystrokes (Life tester)		
	Switch type	Contamination-resistant switch membrane		
	Key-leveling mechanisms	For all double-wide and greater-length keys		
	Cable length	6 ft (1.8 m)		
Environmental	Acoustics	43-dBA maximum sound pressure level		
	Operating temperature	50° to 122° F (10° to 50° C)		
	Non-operating temperature	Minus 30 degress to 60 degress Celsius		
	Operating humidity	10% to 90% (non-condensing at ambient)		
	Non-operating humidity	20% to 80% (non-condensing at ambient)		
	Operating shock	40 g, six surfaces		
	Non-operating shock	80 g, six surfaces		
	Operating vibration	2-g peak acceleration		
	Non-operating vibration	4-g peak acceleration		
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence		
	Drop (in box)) 30 in (76.2 cm) on concrete, 16-drop sequence		
Approvals	UL, FCC, CE Mark, TUV GS, VCCI	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC		
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and TUVGS			



HP USB Business Slim Wire	ed SmartCard CCID Keyboard		
Physical Characteristics	Keys	104, 105, 109 layout (depending upon country)	
	Dimensions (L x W x H)	17.34 x 5.68 x 0.78in (440.6 x 144.5 x 1.98 cm)	
	Weight	1.32 lb (598ց)	
Electrical	Operating voltage	5 VDC, +/-5%	
	Power consumption	100mA (All LED on)	
	System interface	USB Type A plug connector	
	ESD	Contact Discharge: 8 KV Air Discharge: 12.5 KV	
	EMI - RFI	Conforms to FCC rules for a Class B computing device	
Mechanical	Keycaps	Low-profile design	
	Switch actuation	60±10g nominal peak force with tactile feedback	
	Switch life	10 million keystrokes (Life tester)	
	Switch type	Contamination-resistant switch membrane	
	Key-leveling mechanisms	For all double-wide and greater-length keys	
	Cable length	6 ft (1.8 m)	
Environmental	Acoustics	43-dBA maximum sound pressure level	
	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence	
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence	
Approvals	CE Marking, TUV, EAC, FCC, cUL	us/CSAus, ICES, RCM, VCCI, KCC, BSMI	
Ergonomic compliance	ISO 9241-4, TUVGS		



HP 125 (AntiMicrobial) Wi	red Keyboard (China only)		
Physical Characteristics	Keys	104/105/107/109layout (depending upon country)	
	Dimensions (L x W x H)	436 x 138 x24.7 mm	
	Weight	471g	
Electrical	Operating voltage	5V +- 5%	
	Power consumption	50mA	
	System interface	USB Type A plug connector	
	ESD	Contact Discharge: 8 KV Air Discharge: 12.5 KV	
	EMI - RFI	Conforms to FCC rules for a Class B computing device	
Mechanical	Keycaps	Low-profile design	
	Switch actuation	55±10g nominal peak force with tactile feedback	
	Switch life	10 million keystrokes (Life tester)	
	Switch type	Contamination-resistant switch membrane	
	Key-leveling mechanisms	For all double-wide and greater-length keys	
	Cable length	1.8 m	
Environmental	Acoustics	43-dBA maximum sound pressure level	
	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-4° to 149° F (-20° to 65° C)	
	Operating humidity	10% to 95% (non-condensing at ambient)	
	Non-operating humidity	0% to 95% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence	
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence	
Approvals	UL, cUL, FCC, CE, TUV GS, VCCI,	BSMI, RCM, KCC, USB-IF, WHQL, EN/IEC 60601-1	
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and TUVGS		



HP 655 wireless Keyboard	I				
Physical Characteristics	Keys	104, 105, 107,109 layouts			
	Dimensions (L x W x H)	16.86 x 4.55 x 0.71 in (428.22 x 115.47 x 18.06 mm)			
	Weight	0.96 lb (435g)			
Electrical	Operating voltage	3 VDC, +/-5%			
	Power consumption	20 mA Max (All LED on)			
	System interface	2.4GHz Wireless			
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV			
	EMI - RFI	Conforms to FCC rules for a Class B computing device			
Mechanical	Keycaps	Plunger, 2.0 mm key travel			
	Key actuation	60±10g nominal peak force with tactile feedback			
	Key life	10 million keystrokes (Life tester)			
	Key structure type	Rubber dome & Membrane			
	Key-leveling mechanisms	For all double-wide and greater-length keys			
Environmental	Operating temperature	50° to 122° F (10° to 50° C)			
	Non-operating temperature	-22° to 140° F (-30° to 60° C)			
	Operating humidity	10% to 90% (non-condensing at ambient)			
	Non-operating humidity	20% to 80% (non-condensing at ambient)			
	Operating shock	40 g, six surfaces			
	Non-operating shock	80 g, six surfaces			
	Operating vibration	2-g peak acceleration			
	Non-operating vibration	4-g peak acceleration			
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence			
	Drop (in box)	Drop (in box) 30 in (76.2 cm) on concrete, 16-drop sequence			
Approvals	CB, CE, FCC, cULus, ICES, IC, I TRC, TRA, CASA, UA, EAC, CNC, ANATEL, NOM-NYCE SCT, IFETEL, MPTC, RCM, BIS, PosTel, VCCI, TELEC, KC, MCMC, IDA, BSMI, NCC, DWLF&M, TP-BY, MOC				
Ergonomic compliance	TUVGS				

HP Wired Desktop 320K Keyboard		
	Keys	104, 105, 107,109 layouts
Physical Characteristics	Dimensions(L x W x H)	18.86*4.55*0.66 in (426.2 x 110.9 x 16.7 mm)
	Weight	1.00 lb(452g)
	Operating voltage	5 VDC, +/-5%
	Power consumption	50 mA Max (All LED on)
	System interface	USB Port



Ergonomic compliance	TUVGS				
Approvals	CB, CE, FCC, ICES, EAC, NOM-N	B, CE, FCC, ICES, EAC, NOM-NYCE SCT, RCM, BIS, VCCI, KC, BSMI			
	Drop (in box)	10 times drop including 6 faces, one corner and 3 edges on rigid surface Drop Height: 91cm		lges on rigid surface.	
	Drop (out of box)	76cm on carpet, six-drop	sequence		
		500	-	0.0039	
		350-500	-6	-	
	Non-operating vibration	100-137 137-350	-6 0	0.008	
		5.100	0	0.015	
		Frequency (Hz)	Slope (dB/oct)	PSD (g²/Hz)	
		T	otal Test time: 10 minutes		
			(~0.21G _{nms})		
	Operating vibration	500	-0	0.00005	
		5-350 350-500	0 -6	0.0001	
		Frequency (Hz)	Slope (dB/oct)		
		Frequency (U-2)	Slone (dR/oc+)	PSD (g²/Hz)	
Environmental	Operating shock Non-operating shock	i. Half-Sine Shock – End-Use Handling, Non-Operational Sample size: 5pcs. Condition: Sample power off. Axis: X, Y, Z axis (all 6 faces) – sample normal mode of operation. Number of shocks: 1 shock/face. Pulse duration: < 3 ms Velocity change: 50lps (inch-per-second)- 65lps desired. ii. Trapezoidal Shock- Transportation Environment, Non-Operationa Sample size: 5pcs. Condition: Sample power off. Orientation: All six faces: Front, Rear, Left, Right, Bottom, and Top. Configuration: As intended for shipment Number of shocks: 1 shock/face. Minimum faired acceleration: 30G's. Test also at 40 and 50G's to find margin. Velocity change: 266lps (inch-per-second) for product mass (m) 20 <m<40lbs.< td=""><td>of operation. desired. Non-Operational ettom, and Top. and 50G's to find</td></m<40lbs.<>		of operation. desired. Non-Operational ettom, and Top. and 50G's to find	
	Non-operating humidity	10% to 90% (non-conder	ising at ambient)		
	Operating humidity	N/A			
	Non-operating temperature	-30° C to 95° C			
	Operating temperature	10° C to 90° C			
Mechanical	Keycaps	2.0mm +/-0.2mm at 120gf Key travel			
	EMI - RFI	European Standard EN 55022: 2006+A1: 2007, Class B. FCC/CFR 47: Part 15 Class B			
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV (Class B)			



	I				
	Keys	Left/right key			
Physical Characteristics	Dimensions(L x W x H)	4.09 x2.50 x 1.40 in (103.8x 63.4 x 35.5 mm)			
	Weight	0.16 lb(72g)			
	Operating voltage	5 VDC, +/-0.25V			
	Power consumption	100 mA Max			
Electrical	System interface	USB Port			
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV (Class B)			
	EMI - RFI	European Standard EN 55 FCC/CFR 47: Part 15 Class	5022: 2006+A1: 2007, Clas s B	s B.	
	Keycaps	0.3mm key travel			
	Key actuation	75±20g			
Mechanical	Key life	1million cycles			
	Key structure type	Tact Switch			
	Key-leveling mechanisms	N/A			
	Operating temperature	10° to 90° C			
	Non-operating temperature	-30° C to 95° C			
	Operating humidity	N/A			
	Non-operating humidity	10% to 90% (non-condensing at ambient)			
	Operating shock	N/A			
Environmental	Non-operating shock	 i. Half-Sine Shock – End-Use Handling, Non-Operational Sample size: 5pcs. Condition: Sample power off. Axis: X, Y, Z axis (all 6 faces) – sample normal mode of operation. Number of shocks: 1 shock/face. Pulse duration: < 3 ms Velocity change: 50lps (inch-per-second)- 65lps desired. ii. Trapezoidal Shock- Transportation Environment, Non-Operational Sample size: 5pcs. Condition: Sample power off. Orientation: All six faces: Front, Rear, Left, Right, Bottom, and Top. Configuration: As intended for shipment Number of shocks: 1 shock/face. Minimum faired acceleration: 30G's. Test also at 40 and 50G's to find margin. Velocity change: 266lps (inch-per-second) for product mass (m) 20<m<40lbs.< li=""> </m<40lbs.<>		of operation. desired. Non-Operational ottom, and Top. and 50G's to find	
		Frequency (Hz)	Slope (dB/oct)	PSD (g²/Hz)	
		5-350	0	0.0001	
	Operating vibration	350-500 500	-6 -	0.00005	
		300	- (~0.21G _{nms})	0.00003	
		Total Test time: 10 minutes			



		Frequency (Hz)	Slope (dB/oct)	PSD (g²/Hz)
		5.100	0	0.015
	Non-operating vibration	100-137	-6	-
	Their operating violation	137-350	0	0.008
		350-500	-6	-
		500	-	0.0039
	Drop (out of box)	76cm on carpet, six-drop sequence		
	Drop (in box)	N/A		
Approvals	CB, CE, FCC, cULus, ICES, EAC, NOM-NYCE SCT, RCM, VCCI, KC, BSMI			
Ergonomic compliance	TUVGS			

HP 655 wireless Mouse			
Dimensions (H x L x W)	4.74 x 2.75 x 1.63 in (120.29 x 69.97 x41.39 mm)		
Weight	0.194lb (88g)		
Environmental	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
Electrical	Operating voltage	3 VDC, +/-5%	
	Power consumption (typical)	10 mA Max	
	Resolution	1,200 DPI (Default)	
	Sensor	Pixart PAW3222DB-TJDS	
	Tracking speed	10G(max), 1G=9.8m/s2	
	Tracking acceleration	2.4GHz Wireless	
Mechanical	Color	Jack Black	
Regulatory approvals	Compliant	CB, CE, FCC, cULus, ICES, IC, TRC, TRA, ICASA, UA, EAC, CNC, ANATEL, NOM-NYCE SCT, IFETEL, MPTC, RCM, PosTel, VCCI, TELEC, KC, MCMC, IDA, BSMI, NCC, DWLF&M, TP-BY, MOC	
Ergonomic compliance	Compliant	TUVGS	



HP PS/2 Mouse				
Dimensions (H x L x W)	4.53 x 2.48 x1.46 in (115.2x 63 x37 mm)			
Weight	0.22lb (101.6g)	0.22lb (101.6g)		
Environmental	Operating temperature	41° to 122° F (5° to 50° C)		
	Non-operating temperature	(-4° to 140° F)(-20° to 60° C)		
	Operating humidity	10% to 85% (non-condensing at ambient)		
	Non-operating humidity	5% to 95% (non-condensing at ambient)		
	Operating shock	40 g, six surfaces		
	Non-operating shock	80 g, six surfaces		
	Operating vibration	2-g peak acceleration		
	Non-operating vibration	4-g peak acceleration		
Electrical	Tracking speed	30 inch/sec (max)		
	Tracking acceleration	8G(max), 1G=9.8m/s2		
	System interface	PS/2		
Mechanical	Switch actuation	60±15g nominal peak force with tactile feedback		
	Switch life	3 million keystrokes (Life tester)		
	Switch type	Contamination-resistant switch membrane		
	Key-leveling mechanisms	For all double-wide and greater-length keys		
	Cable length	6 ft (1.8 m)		
	Color	Jack Black		
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC		



HP USB 125 (Antimicrobi	al)/128 Laser Mouse (China only)	
Dimensions (H x L x W)	112 x 63 x 36.2 mm (L x W x H)		
Weight	85 g		
Environmental	Operating temperature	50° to 122° F (10° to 50° C)	
	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
Electrical	Operating voltage	5 VDC, +/-5%	
	Power consumption (typical)	100mA	
	Resolution	1,200 DPI	
	Sensor	Optical/ Laser USB mouse sensor	
	Tracking speed	30 inch/sec (max)	
	Tracking acceleration	8G(max), 1G=9.8m/s2	
Mechanical	Connector	USB	
	Cable length	6 ft (1.8 m)	
	Color	Jack Black	
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC, EAC	



Technical Specifications – Audio/Multimedia

AUDIO/MULTIMEDIA

HP Elite Mini 800 G9 Desktop PC

Type Integrated

HD Stereo Codec Realtek ALC3252

Audio I/O Ports combo audio jack with CTIA and OMTP headset support

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speaker.

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 192 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes

HP Elite SFF 800 G9 Desktop PC

Type Integrated
HD Stereo Codec Realtek ALC 3252

Audio I/O Ports Front: Headset connector supports a CTIA and OMTP style headset and is re-taskable as a Line-in,

Line-out, Microphone-in or Headphone-out port

Rear: Line-out, Line-in*, 3.5mm and support stereo and retasking

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speaker.

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes

*NOTE: System default is line-out. Line-in / Line-out can be adjusted through the audio setting



Technical Specifications – Audio/Multimedia

HP Elite Tower 800/880 G9 Desktop PC

Type Integrated
HD Stereo Codec Realtek ALC 3252

Audio I/O Ports Front: Headset connector supports a CTIA and OMTP style headset and is re-taskable as a Line-in,

Line-out, Microphone-in or Headphone-out port

Rear: Line-out, Line-in*, 3.5mm and support stereo and retasking

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speaker.

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 192 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

HP EliteOne 840 23.8 in & 870 27 in G9 All-in-One Desktop PC's

Bang & Olufsen Audio

Type Integrated
HD Stereo Codec Realtek ALC3274

Audio I/O Ports Side headset connector supports a CTIA/OMTP style headset and is re-taskable as a Line-in, Line-

out, Microphone-in or Headphone-out port All ports are 3.5mm and support stereo

Internal Speaker Amplifier 5W per channel class D stereo amplifier for the internal speakers only

Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speakers.

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 192 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes - Stereo



^{*}NOTE: System default is line-out. Line-in / Line-out can be adjusted through the audio setting

Technical Specifications – Integrated Webcam and Microphone

INTEGRATED WEBCAM AND MICROPHONE

Integrated Webcam and Microphone

Optional integrated 5 MP Swivel Webcam with integrated dual array digital microphones

Optional integrated 5 MP Swivel Webcam + IR Sensor + Color Light Sensor with integrated dual array digital microphones (Supports Windows Hello)

Optional integrated 16MP binned Swivel Webcam + IR Sensor + Color Light Sensor + Time of Flight Sensor (TOF) (Supports Windows Hello)

NOTE: All HP devices which carry the Bang & Olufsen brand are custom-tuned with Bang & Olufsen's acoustical engineers for precise sound experience in business use.

INTEGRATED FINGERPRINT SENSOR

Sensor type: Touch

Fingerprint matching: Performed on device

Anti-Spoofing: Yes

Windows Hello Support: Yes Encryption: On sensor FIPS Compliant: No



Technical Specifications – Power

POWER

HP Elite Mini 800 G9 Desktop PC (35W)

Unit Environment and Operating Conditions

Temperature Range Operating: 5°C ~35°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

HP Elite Mini 800 G9 Desktop PC (65W)

Unit Environment and Operating Conditions

Temperature Range Operating: 5°C ~35°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

HP Elite SFF 800 G9 Desktop PC

Unit Environment and Operating Conditions

Temperature Range Operating: 5°C ~35°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

HP Elite Tower 800 G9 Desktop PC

Unit Environment and Operating Conditions

Temperature Range Operating: 5°C ~35°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)

HP EliteOne 840 23.8 in & 870 27 in G9 All-in-One Desktop PC

Unit Environment and Operating Conditions

Temperature Range Operating: 5°C ~45°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft. (15240 m)



Technical Specifications – Power

	<u>Mini</u>	SFF	TWR	AiO
External Power Supplies ¹	90W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac 120W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac 150W EPS, active PFC, 88% efficiency in 115Vac / 89% efficiency in 230Vac 180W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac 200W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac	N/A	N/A	N/A
80 PLUS Platinum		260W active PFC / 80 PLUS Platinum 400W active PFC / 80 PLUS Platinum Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V	550W active PFC / 80 PLUS Platinum 260W active PFC / 80 PLUS Platinum 400W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	240W active PFC / 80 PLUS Platinum 280W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)
Operating Voltage Range	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac
Rated Line Frequency	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ
Operating Line Frequency	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ
Rated Input Current with Energy Efficient* Power Supply	90W≦1.7A 120W≦1.7A 150W≦2.5A 180W≦2.5A 200W≦3.0A	260W Platinum≤3.1A 400W Platinum≤5.2A	260W Platinum≤3.1A 400W Platinum≤5.2A 550W Platinum≤6.6A	240W≦3.0A 280W≦3.2A
DC Output	+19.5V	+12V	+12V	+20V

^{1.} External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.



Technical Specifications – Power

	<u>Mini</u>	SFF	TWR	AiO
99: 2012)	Less than 500 microamps of leakage current at 264 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 264 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 500 microamps of leakage current at 264 Vac with the ground wire disconnected, as required for Non- patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 264 Vac with the ground wire intact with normal polarity, as required for Non- patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section	Less than 500 microamps of leakage current at 264 Vac with the ground wire disconnected, as required for Non- patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 264 Vac with the ground wire intact with normal polarity, as required for Non- patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in	Less than 500 microamps of leakage current at 264 Vac with the ground wire disconnected, as required for Non- patient Electrical Appliances and Equipment used in a patient care facility or
Power Supply Fan	N/A	70 mm variable speed	70 mm variable speed	N/A
Power cord length	6.0 ft. (1.83 m) ^{1,2}	6.0 ft. (1.83 m) ²	6.0 ft. (1.83 m) ²	6.0 ft. (1.83 m) ^{1,2}
External Power Adapter	External power	Internal power	Internal power supply	Internal power supply
Dimensions	90W: 126 x 50 x 30mm 120W: 138 x 68.5 x 25.4 mm 150W: 148 x 75.5 x 25.4 mm 180W: 165.5 x 79 x 25.4 mm 200W: 165.5 x 79 x 25.4 mm		165 x 95 x 73 mm	90 x 130 x 26 mm
Total Cord Length	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)

^{1.} Power cord length will be varied from different type of cords start from 1.8m.

^{2.} The length of India power cord is 2.0m

Technical Specifications – Power

AC Adaptor		Eris+ 200W	
Dimensions		6.5 x 3.11 x 1.0 in (16.5 x 7.9 x 2.54 cm)	
Weight		530 g (+/- 10 g)	
Input Efficiency		Average Efficiency of 25%, 50%, 75%, 100% load condition with 115 Vac / 230 Vac Spec: 88% at 115 Vac and 89 % at 230 Vac	
	Input Frequency Range	47-63 Hz	
	Input AC current	Max. 3.0 A at 90 Vac	
Output	Output Power	200W	
	DC Output	19.5V	
	Hold-up Time	5 ms at 115 Vac input	
	Output Over Current Protection	< 21.0A	
Leakage Current		Shall not exceed 50uA when tested at 250 Vac/50 Hz in a normal operating condition	
AC connector (Ac Inlet)	C14	
DC Plug		7.4 mm Barrel Type	
	Operating Temperature	32°F to 95°F (0° to 35°C)	
Design	Non-operating (storage) Temperature	-4°F to 185°F (-20° to 85°C)	
	Altitude	0 to 16,400 ft (0 to 5000 m)	
	Humidity	20% to 95%	
Storage Humidity		10% to 95%	
EMI and Safety Certifications		*CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950-1 and/or IEC62368-1 2&3 ed, EN60950-1 and/or EN62368-1, UL62368-1, Class I, SELV; Agency approvals - cULus, CCC, BIS, PSE(J62368), EN55032 Class B, FCC Class B, CISPR32 Class B, CCC, NOM-001 NYCE, EAEU, Australia MTBF - over 100,000 hours at 35°C ambient condition	

HP EliteOne 840 23.8 in & 870 27 in G9 All-in-One Desktop PC

Wireless Charger General Description

Operating Voltage	12~13V (DC) After QI certificate, this range are optimum voltage.		
Nominal Input voltage	2.6V (DC) (The optimum working voltage)		
Input Current	Typ. 1.5A (2A max.)		
Max Input Power	<24W		
Standby Current (No load)	Averrage current=12.5mA Max. (Q/Ping period= 500ms Avg. Power 150mW Max.)		
Over Voltage Protection	15V Max.		
Over Current Protection	2.1A± 10%		



Technical Specifications – Power

The power supply shall comply with harmonic input current requirements as detailed in EN61000-3-2 and JEIDA MITI standards. The harmonic input current requirements must be met under the following operating conditions:

Load Requirements: 50% and 100%

Input Voltage: 230Vac/50Hz.

For active power factor correction the power factor at 50% &100% loads shall be greater than 0.9 over the entire nominal input voltage range (100-127VAC and 200-240VAC).

Condition	Standard Efficiency	82/85/82%	85/88/85%	87/90/87%	90/92/89%	Input Voltage
10% of Rated Load	-	75%	81%	84%	86%	115Vac/60HZ
20% of Rated Load	-	82%	85%	87%	90%	115Vac/60HZ
50% of Rated Load	-	85%	88%	90%	92%	115Vac/60HZ
	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.95	
100% of Rated	70%	82%	85%	87%	89%	115Vac/60HZ
Load	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.9	230Vac/50HZ



Technical Specifications – Weights and Dimensions

WEIGHTS & DIMENSIONS

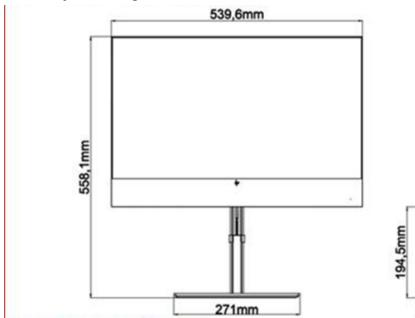
	<u>Mini</u>	SFF	TWR	AiO
Chassis (W x D x H)	6.97 x 6.89 x 1.35 in 177 x 175 x 34 mm	12.12 x 13.3 x 3.94 in 308x 338 x 100 mm	6.1 x 12.13 x 13.27 in 155 x 308 x 337 mm	See table below.
System Volume	63.4 cu in 1.05L	635.11 cu in 10.4 L	981.9 cu in 16.1 L	See table below.
System Weight	3.13 lb 1.42 kg	11.11 lb 5.04 kg	13.56 lb 6.15 kg	See table below.
Max Supported Weight (desktop orientation)	0	77 lb 35 kg	77 lb 35 kg	See table below.
Stand Dimensions	160 x 117 x 18.5 mm	151.8 x 200 x 37.2mm	N/A	See table below.
Packaging (W x D x H)	19.6 x 5.2 x 9.3 in 498 x132 x 235 mm	15.71 x 19.65 x 9.06 in 399 x 499 x 230 mm MPP: 15.71 x 19.65 x 9.06 in (399 x 499 x 230 mm)	15.75 x 19.65 x 11.30 in (400 x 499 x 287 mm) MPP : 15.75 x 19.65 x 11.30 in (400 x 499 x 287 mm)	See table below.
Shipping Weight	2.95 kg 6.49 lb	17.0 lb (7.72 kg) MPP: 17.44 lbs (7.92 kg)	19.54 lbs (8.87 kg) MPP : 20.35 lbs (9.24kg)	See table below.
Multipack Packaging (10 units)	20.28 x16.54 x 25 in 515 x 420 x 636 mm	6 units per layer 10 layers max 60 units per pallet 1200 x 1000 x 2438 mm (include the pallet)	6-units per layer 8 layer max 48 per pallet 47.24 x 39.37 x 95.12 in, 1200 x 1000 x 2416 mm (including pallet)	
Palletization Profile	10-units per layer 10 layers max 100 units per pallet 46.3 x 39.2 x 57.7 in, 1175 x 996 x 2125 mm (including pallet)	6 units per layer 10 layers max 60 units per pallet 1200 x 1000 x 2438 mm (include the pallet)	6-units per layer 8 layer max 48 per pallet 47.24 x 39.37 x 95.12 in, 1200 x 1000 x 2416 mm (including pallet)	10-units per layer 4-layers max 40-units per pallet (sea) 1200 x 1000 x 2470 mm

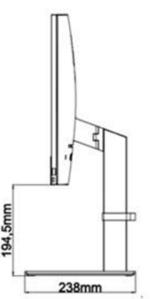


Technical Specifications – Weights and Dimensions

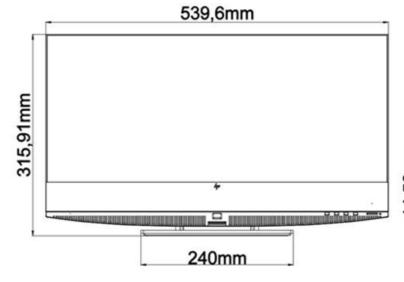
STANDS AND DIMENSIONS

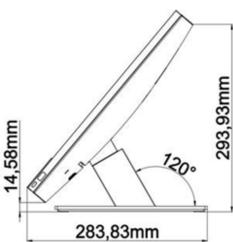
HP EliteOne G9 AIO Adjustable Height Stand - 23.8"





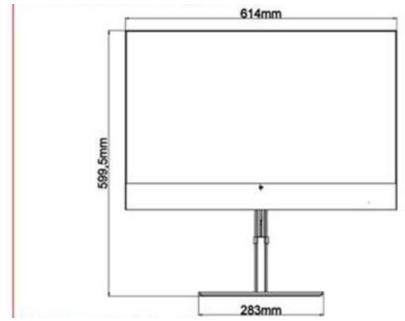
HP EliteOne G9 AIO Recline Stand - 23.8"

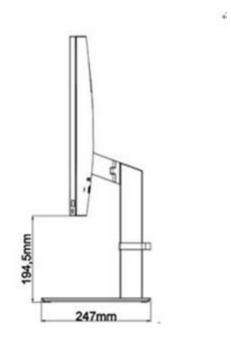




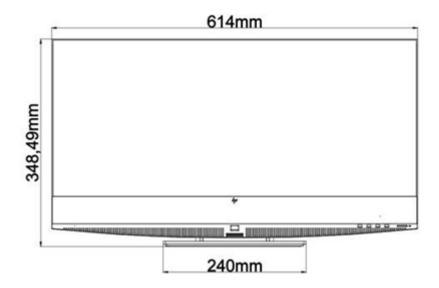
Technical Specifications – Weights and Dimensions

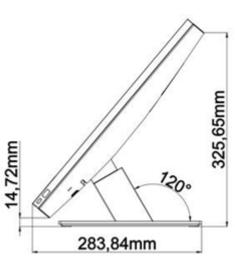
HP EliteOne G9 AIO Adjustable Height Stand - 27"





HP EliteOne G9 AIO Recline Stand - 27"





Adjustable Height Stand:	Height - Vertical/Landscape Adjustment	130mm (±2 mm)
	Portrait Adjustment	No portrait
	Tilt Angle	-5° to +18° (±2°) in landscape and portrait
	Rotation (Swivel)	86° (±4°) (45 left, 45 right)
	Pivot	No pivot

Recline Stand:	Height - Vertical Adjustment	No height	
	Tilt Angle	+35°(+3°/-0°) to +60° (+/-3°)	
	Rotation (swivel)	No swivel	

Technical Specifications – Weights and Dimensions

ALL-IN-ONE WEIGHTS AND DIMENSIONS

Weight without Touch Panel - 23.8"

Product Weight (DIS) Unboxed	Without Stand 15.39 lbs. 6.98kg	Adjustable Height Stand (WLC) 20.55 lbs. 9.32 kg Adjustable Hight Stand 20.42 lbs 9.26 kg	Recline Stand 18.96 lbs. 8.6 Kg	
Shipping Weight Boxed EPE	Without Stand 22.22 lbs. 10.08 kg	Adjustable Height Stand 27.56 lbs. 12.5 kg	Recline Stand 25.93 lbs. 11.76 kg	
Shipping Weight Boxed MPP	Without Stand 22.3 lbs. 10.12 kg	Adjustable Height Stand 27.64 lbs. 12.54 kg	Recline Stand 26.01 lbs. 11.8 kg	
Shipping Weight Pallet (30 units) EPE	Without Stand 666.6 lbs. 302.4 kg	Adjustable Height Stand 826.8 lbs. 375 kg	Recline Stand 777.79 lbs. 352.8 kg	
Shipping Weight Pallet (30 units) MPP	Without Stand 669 lbs. 303.6 kg	Adjustable Height Stand 829.2 lbs. 376.2 kg	Recline Stand 780.3 lbs. 354 kg	

Weight with Touch Panel - 23.8"

Product Weight Unboxed	Without Stand 14.59 lbs. 6.62 kg	Adjustable Height Stand (WLC) 19.75 lbs. 8.96 kg Adjustable Height Stand 19.62 lbs 8.9 kg	Recline Stand 18.16 lbs. 8.624Kg
Shipping Weight Boxed EPE	Without Stand 24.6 lbs. 11.16 kg	Adjustable Height Stand 29.94 lbs. 13.58 kg	Recline Stand 28.31 lbs. 12.88 kg
Shipping Weight Boxed MPP	Without Stand 24.68 lbs. 11.2 kg	Adjustable Height Stand 30.02 lbs. 13.62kg	Recline Stand 28.39 lbs. 12.88 kg
Shipping Weight Pallet (30 units) EPE	Without Stand 738 lbs. 334.8 kg	Adjustable Height Stand 898.2 lbs. 407.4 kg	Recline Stand 849.3 lbs. 385.2 kg
Shipping Weight Boxed MPP	Without Stand 740.4 lbs. 336 kg	Adjustable Height Stand 900.6 lbs. 408.6 kg	Recline Stand 851.7 lbs. 386.4 kg



Technical Specifications – Weights and Dimensions

Dimensions (W x D x H) - 23.8"

Product			Recline Stand
Dimensions	539.6 x52.3 x386.63 mm	Stand (-5 ~ 20) degrees	Stand (30 ~ 60) degrees
(Non-touch)		539.6x238x558.1 mm	539.6x283.82x315.91 mm
Product	Without Stand	Adjustable Height	Recline Stand
Dimensions	539.6x52.3x386.63 mm	n Stand (-5 ~ 20) degrees Stand (30 ~ 60) o	
(In-cell Touch)		539.6x238x558.1 mm	539.6x283.83x315.91 mm

Shipping Dimensions – 23.8"

- 11 3	.,	Recline Stand 628 x 186 x 675 mm
Shipping Dimensions Pallet Pallet (30 units)		Recline Stand 1180 x 874 x 2180 mm



Technical Specifications – Weights and Dimensions

Weight without Touch Panel - 27"

Shipping Weight Boxed EPE: 2.73 kg	Without Stand 18.58 lbs. 8.43 kg	Adjustable Height Stand 23.98 lbs. 10.88 kg	Recline Stand 23.74 lbs. 10.77 kg
Shipping Weight Boxed Hybrid : 4351 g	Without Stand 27.38 lbs. 12.42 kg	Adjustable Height Stand 33.22 lbs. 15.07 kg	Recline Stand 31.09 lbs. 14. 10kg
Shipping Weight Pallet (18 units) EPE: 2210 g	Without Stand 426.59 lbs. 193.5 kg	Adjustable Height Stand 531.75 lbs. 241.2 kg	Recline Stand 493.26 lbs. 223.74 kg
Shipping Weight Pallet (18 units) Hybrid : 4351 g	Without Stand 492.86 lbs. 223.56 kg	Adjustable Height Stand 598.025 lbs. 271.26 kg	Recline Stand 559.53 lbs. 253.8 kg

Weight with Touch Panel - 27"

Product Weight Unboxed	Without Stand (QHD DIS) 23.70 lbs. 10.75 kg	Adjustable Height Stand 29.54 lbs. 18.41 kg	Recline Stand 27.40 lbs. 12.43 Kg
Shipping Weight Boxed	Without Stand 23.70 lbs. 10.75 kg	Adjustable Height Stand 29.54 lbs. 13.4 kg	Recline Snd 27.40 lbs. 12.43 kg
Shipping Weight Pallet (18 units)	Without Stand 465.3 lbs. 211.5 kg	Adjustable Height Stand 570.24 lbs. 259.2 kg	Recline Stand 531.83 lbs. 241.74 kg

Dimensions (W x D x H) - 27"

Pinionerone (III X P X I	-, -:				
Product	Without Stand	Adjustable Height	Recline Stand		
Dimensions	614 x 52.3 x 428.2 mm	Stand (-5 ~ 20) degrees Stand (35 ~ 60) degrees			
(Non-touch)		614 x 247 x 599.5mm	614 x 283.83x 348.49mm		
Product	Without Stand	Adjustable Height	Recline Stand		
Dimensions	614 x 52.3 x 428.2 mm	Stand (-5 ~ 20) degrees	Stand (35 ~ 60) degrees		
(In-cell Touch)		614 x 247 x 599.5mm	614 x 283.83x 348.49mm		

Shipping Dimensions - 27"

- 11 3	742 x 237 x 640 mm	, , ,	Recline Stand 742 x 237 x 640 mm		
Shipping Dimensions Pallet Pallet (18 units)			Recline Stand 1180 x 958 x 2076 mm		



Technical Specifications – Miscellaneous Features

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode.
 Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel® Wired for Management support; industry wide initiative to make Intel® architecture based PCs, servers and mobile
 computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
 - Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initially):
 - 2 red + 2 white User must provide file for BIOS recovery (USB storage typically)
 - 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
 - 2 red + 4 white BIOS recovery is in progress
 - 3 red + 2 white Memory could not be initialized
 - 3 red + 3 white Graphics adaptor could not be found
 - 3 red + 4 white Power supply failure / not connected
 - 3 red + 5 white Processor not installed
 - 3 red + 6 white Current processor does not support an enabled feature
 - 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
 - 4 red + 3 white System internal temperature has exceeded its threshold
 - 5 red + 2 white System controller firmware is not valid
 - 5 red + 3 white System controller detected BIOS is not executing
 - 5 red + 4 white BIOS could not complete initialization / PCA failure
 - 5 red + 5 white
 System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:
 - This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- 1 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal (For MT, SFF, and DM only)
- Green Pull Tabs, and Quick Release Latches for easy Identification



Technical Specifications – Miscellaneous Features

Additional Features	Description
Tower Orientation	Product can be oriented as either a desktop (horizontal) or a tower (vertical) for Tower, SFF, and Mini only. SFF/Mini requires optional stand.
Drive Lock	Implementation of the industry standard ATA Security feature set. When enabled, it prevents software access to user data on the drive until one or two user-defined passwords are provided.
Boot Sectors Protection	MBR and GPT sectors of the hard drive are critical to booting the operating system. By saving the MBR or GPT data (depending on the how the OS was installed), the BIOS will be able to monitor for changes and allow the user to override them with the backup copy at boot-up.
Drive Protection System	DPS Access through F10 Setup during Boot (for SATA hard drive only)
	A diagnostic hard drive self- test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user
	Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be replaced
	The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types of failures
SMART Technology (Self-Monitoring, Analysis and Reporting Technology)	Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted
SMART I - Drive Failure Prediction	Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count
SMART II - Off-Line Data Collection	By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure
SMART III - Off-Line Read Scanning with Defect Reallocation	IOEDC: I/O Error Detection Circuitry
SMART IV - End-to-End CRC for hard drives	Detects errors in Read/Write buffers on HDD cache RAM

Technical Specifications – After Market Options

AFTER MARKET OPTIONS

HP Presence Accessories	<u>Mini</u>	<u>SFF</u>	TWR	<u>AiO</u>	Part Number
HP Presence Hub	X				4V977AA
HP Presence Audio Video Bar	X				4V974AA
HP Presence See 4K AI Camera	X				4V975AA
HP Presence Talk Satellite Microphones (2)	X				4V976AA
HP Presence No Audio Control Center	X				4V978AA
HP Presence 15m Type-C Cable Kit	X				4V972AA
HP Presence 30m Type-C Cable Kit	X				4V973AA
HP Presence Control Table Mount Kit	X				4V979AA
HP Presence See Table Lock Kit	X				54N70AA
HP Presence Control Table Wall Mount Kit	X				4V980AA

Graphics Solutions	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
NVIDIA T400 2GB GDDR6 3mDP		Х	X		340K8AA
NVIDIA T600 4GB GDDR6 4mDP		X	X		340K9AA
HP DisplayPort to HDMI True 4k Adapter	Х	X	X	X	2JA63AA
HP DVI Cable Kit		X	X		DC198A
HP HDMI Standard Cable Kit	Х	Х	X	X	T6F94AA
HP DisplayPort to VGA Adapter	Х	X	X	X	AS615AA
HP DisplayPort to DVI-D Adapter	Х	X	X	X	FH973AA
HP USB-C To DisplayPort Adapter	Х	X	X	X	N9K78AA
HP Single Mini Display Port Adapter to Display Port Adapter	X				2MY05AA

Desktop Mini Accessories	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP Desktop Mini Port Cover v3	X (Discrete GPU skus not supported)				13L69AA
HP Desktop Mini 2.5" SATA Drive Bay kit v2	X (Discrete GPU skus not supported)				13L70AA
HP Desktop Mini 90W Power Supply Kit	Х				L4R65AA
HP Desktop Mini Lock Box V2	X (Discrete GPU skus not supported)				3EJ57AA
HP Desktop Mini DVD-Writer ODD Expansion Module	Х				K9Q83AA
HP Desktop Mini Security/Dual VESA Sleeve v3	X (95W and discrete GPU skus not supported)				13L67AA
HP Desktop Mini Security/Dual VESA Sleeve v3 with Power Supply Holder	X (Discrete GPU skus not supported)				13L68AA



Technical Specifications – After Market Options

Ir-	1			
HP B250 PC Mounting Bracket	X			<u>8RA46AA</u>
HP B300 PC Mounting Bracket	X			<u>2DW53AA</u>
HP B300 PC Mounting Bracket with Power Supply Holder	X (Discrete GPU skus and 150W/180W adapter not supported)			<u>7DB37AA</u>
HP Desktop Mini Vertical Chassis Stand	X			<u>G1K23AA</u>
HP DM Power Supply Holder Kit v2	X (Discrete GPU skus and 150W/180W adapter not supported)			<u>7DB38AA</u>
HP 150W Elite Mini EPS Holder*	X			<u>657R3AA</u>
HP Quick Release Bracket 2	X		X	<u>6KD15AA</u>
HP Single Monitor Arm	X		X	<u>BT861AA</u>
HP Integrated Work Center Stand 5	X			<u>G1V61AA</u>
HP B550 PC Mounting Bracket	X			<u>16U00AA</u>

NOTE*: Compatible with HP B300 PC Mounting Bracket (2DW53AA) and HP Desktop Mini Security Dual/VESA Sleeve v3 (13L67AA).

AIO Accessories	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP EliteOne G9 VESA Plate				X	6H1W8AA

Data Storage Drives	<u>Mini</u>	<u>SFF</u>	TWR	<u>AiO</u>	<u>Part Number</u>
HP PCIe NVME TLC M.2 256GB SSD	X	X	X	Х	1CA51AA
HP PCIe NVME TLC M.2 512GB SSD	X	X	Х	Х	X8U75AA
HP PCIe Gen 4 NVME TLC M.2 512GB SSD	X	X	X		406L8AA
HP PCIe Gen 4 NVME TLC M.2 1TB SSD	X	X	X		406L7AA
HP 500GB 7200PRM SATA 3.5" Hard Drive		X	X		QK554AA
HP 1TB 7200rpm SATA 3.5" Hard Drive		X	X		QK555AA

Input Devices	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	Part Number
HP 125 Wired Keyboard	X	X	X	X	266C9AA
HP 225 Antimicrobial Wired Mouse and Keyboard Combo (China only)	х	X	Х	Х	286K3AA
HP 225 Wired Mouse and Keyboard Combo	X	X	X	Х	286J4AA
HP 125 Wired Mouse	X	X	X	X	265A9AA
HP 128 Laser Wired Mouse	X	X	X	X	265D9AA
HP Wired Desktop 320K Keyboard	X	X	X	X	9SR37AA
HP Wired Desktop 320M Mouse	Х	Х	X	X	9VA80AA
HP Wired Desktop 320MK Mouse and Keyboard	X	X	X	X	9SR36AA
HP USB Business Slim CCID SmartCard Keyboard	Х	Х	X	X	Z9H48AA
HP 655 Wireless Keyboard and Mouse Combo	X	X	X	X	4R009AA
HP 455 Programmable Wireless Keyboard	Х	X	X	Х	4R177AA



Technical Specifications – After Market Options

System Memory	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP 8GB DDR5-4800 UDIMM		X	X		TBD
HP 16GB DDR5-4800 UDIMM		X	X		TBD
HP 32GB DDR5-4800 UDIMM		X	X		TBD
HP 8GB DDR5-4800 SODIMM	X			X	TBD
HP 16GB DDR5-4800 SODIMM	X			X	TBD
HP 32GB DDR5-4800 SODIMM	X			X	TBD

Multimedia Devices	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	Part Number
HP S101 Speaker Bar	X	X	X		5UU40AA
HP Stereo 3.5mm Headset G2	X	X	X	Х	428K7AA
HP Stereo USB Headset G2	Х	Х	Х	Х	428K6AA
HyperX Cloud MIX – Gaming Headset (Black-Gunmetal)	Х	X	X	X	4P5K9AA
HyperX Cloud Flight – Wireless Gaming Headset (Black-Red)	Х	X	Х	X	4P5L4AA
HyperX Cloud Stinger Core – Gaming Headset (Black)	Х	Х	X	Х	4P4F4AA
HyperX Cloud Core + 7.1 Gaming Headset (Black)	X	Х	X	Х	4P4F2AA
HyperX SoloCast USB WHT Microphone (Black)	Х	Х	Х	Х	4P5P8AA

Security Devices	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	<u>Part Number</u>
HP Business PC Security Lock v3 Kit		X	X	X	3XJ17AA
HP Keyed Cable Lock 10mm	Х	Х	X	X	T1A62AA
HP Master Keyed Cable Lock 10mm	Х	Х	X	X	T1A63AA
HP Sure Key Cable Lock	Х	Х	X	X	6UW42AA

I/O Devices	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	Part Number
HP DisplayPort Port Flex IO v2	Х	X	X		13L54AA
HP Type-C® USB 3.1 Gen2 Port Flex IO v2		X	X		13L59AA
HP USB 3.1 Gen1 x2 Module Flex IO v2	X (Not Available on discrete GPU SKUs)	х	X		13L58AA
HP VGA Port Flex IO v2	Х	Х	X		13L53AA
HP Serial Port Flex IO v2	X (Not Available on discrete GPU SKUs)	х	Х		13L56AA
HP Serial Port Flex IO 2 nd v2	X (Not Available on discrete GPU SKUs)				13L57AA
HP Internal Serial Port (in rear wall)		Х	X		3TK82AA
HP PCIe x1 Parallel Port Card		Х	X		N1M40AA
HP Serial/PS/2 Adapter Kit (in PCIe slot)		Х	X		1VD82AA
HP USB to Serial Port Adapter	X	X	X	X	J7B60AA
HP USB-C to Display Port Adapter	X	X	X	Х	N9K78AA



Technical Specifications – After Market Options

HP Single Mini Display Port Adapter to Display Port Adapter	X (Only Available with GPU SKUs)				2MY05AA
HP USB Type-C Extension Cable Kit (5M)	Х	X	X	Х	9JH45AA
HP Serial Port v3 Flex IO	Х	X	X		5B895AA
HP TBT v3 Flex IO	X	Х	X		440A5AA
HP HDMI Port Flex IO v2	Х	X	X		13L55AA
HP Parallel Port Adapter	X	X	X		KD061AA

NOTE: For more detail on HP I/O Devices please refer to the HP FLEX IO Option Cards QuickSpecs. URL is: http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06042607

Communication Devices	<u>Mini</u>	<u>SFF</u>	<u>TWR</u>	<u>AiO</u>	Part Number
Intel® Ethernet I225-T1 GbE NIC		X	Х		406L9AA
Intel Wi-Fi 6 AX200 ax 2x2 + BT5 non-vPro		Х	Х		TBD



Change Log

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Date	Version History	Action	Description of Change
March 8, 2022	From v1 to v2	Addition	Environmental tables for all platforms added
March 9, 2022	From v2 to v3	Correction / removal	T400 2GB from 4xmDP to 3xmDP connectors corrected / HP Presence Accessories removed from AMO section
March 22, 2022	From v3 to v4	Correction	870 G9 Environmental table corrected
March 23, 2022	From v4 to v5	Correction	ODD's removed from AiO's environmental tables
April 23, 2022	From v5 to v6	Correction	Infineon SLB9670 to SLB9672
April 28, 2022	From v6 to v7	Correction	Slots for splendor corrected / Optional Discrete Graphics Solutions disclaimers updated.
May 17, 2022	From v7 to v8	Correction	Power supply section corrections on pages 89 and 90
May 18, 2022	From v8 to v9	Addition	Eris+ 200W Power supply table added
May 23, 2022	From v9 to v10	Correction	Call out n.2 in AiO side view corrected to 20 from 10Gbps
May 26, 2022	From v10 to v11	Addition	Mark added to Memory section table and notes
June 6, 2022	From v11 to v12	Addition	HP Flex 1GbE Fiber LC Single Port table added to Networking and Communications section
June 7, 2022	From v12 to v13	Addition	200W power supply values added to tables on Power section
June 9, 2022	From v13 to v14	Removal	Call outs section header corrected – Page 9 / Environmental tables certifications updated
June 27, 2022	From v14 to v15	Addition	Power consumption bullet added to At a glance section
July 20, 2022	From v15 to v16	Correction	Made in Desktop Mini Accessories table, in AMO section
July 26, 2022	From v16 to v17	Update	At a glance section updated
August 2, 2022	From v17 to v18	Update	At a glance section updated
August 3, 2022	From v18 to v19	Update	NVIDIA® GeForce® RTX 3060 LHR Graphics Card specs added
August 18, 2022	From v19 to v20	Update	Max. Resolution specs for DM in graphics section updated
August 22, 2022	From v20 to v21	Removal	DVD writers for SFF and Tower removed from AMO section
August 31, 2022	From v21 to v22	Addition	AIO Accessories table added to AMO section
September 7, 2022	From v22 to v23	Update	Weight corrected for SFF and TWR in Weights and Dimensions section
September 28, 2022	From v23 to v24	Update	Note added to SFF and TWR specs in Audio/Multimedia section
October 14, 2022	From v24 to v25	Update	Disclaimer #4 added to rear call outs DT Mini section
October 18, 2022	From v25 to v26	Update	Declared Noise Emissions specs for SFF and TWR updated
October 25, 2022	From v26 to v27	Update	Desktop Mini Accessories table in AMO section updated
October 27, 2022	From v27 to v28	Addition	HP 150W Elite Mini EPS Holder and note added to DM accessories table in AMO section.

